

This document describes the Renesas Connectivity Production Line Tool. The Connectivity PLT hardware, as well as various software applications, are explained in detail. The purpose of this document is to guide users in the setup and operation of the tool. Please add functional and/or application names in keywords in Advanced Properties of the Word file.

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1. Terms and Definitions

BDA Bluetooth® Device Address
Bluetooth LE Bluetooth® Low Energy
BT Classic Bluetooth® Classic

CS Configuration Script (a Renesas DA14xxx devices memory area related to production testing)

DMM Digital Multi Meter

DIP Switch Dual in-line package switches

DUT Device Under Test
HCI Host Controller Interface
PLT Production Line Tool
RF Radio Frequency

RFTU Radio Frequency Test Unit

2. References

- [1] DA14531 Datasheet, Renesas Electronics.
- [2] DA14535 USB kit DA14535-00FXDEVKT-U.
- [3] DA14695 USB kit DA14695-00HQDEVKT-U.
- [4] https://www.microchip.com/en-us/development-tool/sam-ba-in-system-programmer
- [5] https://www.ni.com/en/support/downloads/drivers/download.ni-visa.html#565016

Note 1 References are for the latest published version, unless otherwise indicated.

3. Introduction

The Renesas Connectivity PLT is designed to test, calibrate, and perform memory operations for multiple devices under test (DUTs) in parallel. Specifically, up to four Connectivity PLT boards with eight test sites each can be daisy chained to achieve 32 test sites.

The following parts are delivered with the tool:

- Hardware:
 - Main board (Figure 1)
 - Power cable
- Software:
 - Installation package for Windows environment
- Documents
 - User manual
 - · Electrical schematics
 - Gerber files
 - Bill of Materials.

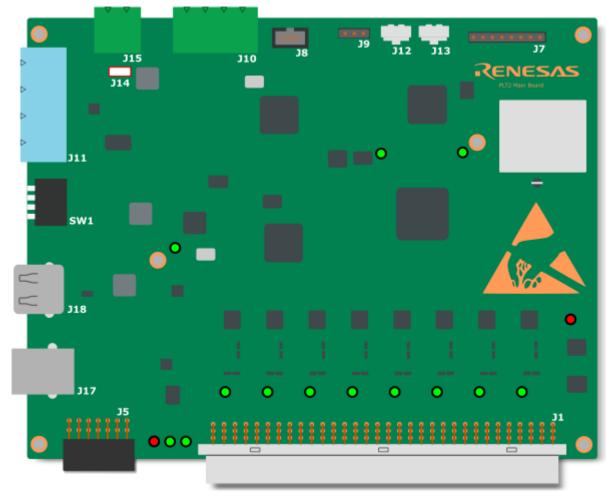


Figure 1. Main board

4. System Overview

4.1 Typical Setup

The Connectivity PLT is a configurable tool that can be adapted to the needs of the production line. Figure 2 shows a simple configuration that consists of a single Connectivity PLT board with eight connected DUT's powered by an external power supply. The host PC is connected to the Connectivity PLT board and to an RF test unit (in this case the SmartBond™ DA14695 Bluetooth® Low Energy 5.2 USB Development Kit). The host has a connected screen so it can run the Connectivity PLT execution application.

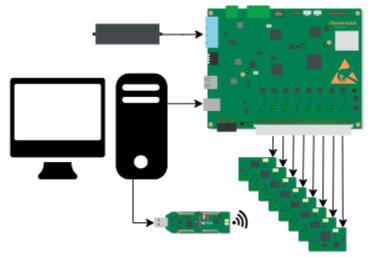


Figure 2. Basic setup

4.2 Typical Test Sequence

The tool performs the following actions:

- 1. The production test firmware is downloaded to the DUT.
- 2. Factory timestamp is read from OTP.
- 3. Automatic crystal (XTAL) trimming is performed.
- 4. RF RSSI RX tests are performed.
- 5. Advertise scan test is performed.
- 6. Flash programmer firmware is downloaded to RAM
- 7. The (customer) application firmware is downloaded (into OTP, QSPI flash).
- 8. The OTP Configuration Script and Header are written to OTP.
- 9. OTP and Flash memory are read back for verification.
- 10. DUTs are powered down.

All actions are performed at the same time on all DUTs up to 32 devices.

5. Hardware Setup

5.1 Power Supply Connections

The Connectivity PLT is designed for use with an external power supply connected to J11. The type of connector is a four-pin terminal block (TBP01R1W-508-04BE). Table 1 shows the requirements for this power supply, and Figure 3 shows the pinout of J11, indicating that the power connector allows for daisy chaining.

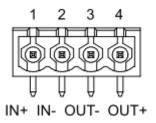


Figure 3. Power Connector J11

Table 1. Power supply characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit
Vin	Input supply voltage		11	12	15	V
lin	Input supply current	Single Connectivity PLT board	2			Α
I _{IDLE}	IDLE current draw	Single Connectivity PLT board		200		mA

5.2 DUT Connections

The DUT connector is an interface for up to eight application boards that can be connected. The type of connector is a 96pin DIN 41612 male connector from Amphenol (86093967113745ELF). Mating parts can be found on the producer's website. The power and the signals to the application board go through this connector. The connector is divided into eight sections, one section per DUT (Figure 4). The pin layout of each section is the same and can be found in Figure 5.

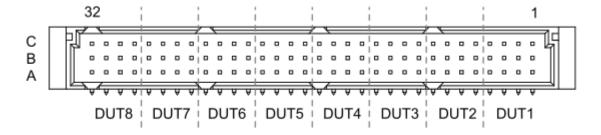


Figure 4. DUT connector

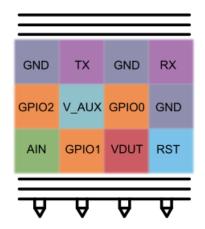


Figure 5. DUT connector pin layout

Table 2. DUT connection characteristics

Parameter	Description	Conditions	Min	Typical	Max	Unit
V _{DUT}	Configurable DUT supply voltage		1.1		5.0	V
I _{DUT}	DUT current	Independent of V _{DUT}			300	mA
V _{AUX}	Configurable Auxiliary voltage		0		5.0	V
laux		1 kΩ series resistor			1	mA
AIN	Analog input voltage		0		5.0	V
	Input impedance			830		kΩ
	ADC resolution (LSB)			1.25		mV
V _{GPIO}	Configurable GPIO voltage		1.2		3.3	V
V _{GPIO_OUT}	GPIO out high voltage	Percentage of V _{GPIO}	70			%
	GPIO out low voltage	Percentage of V _{GPIO}			30	%
IGPIO_OUT	GPIO output current	Depends on FPGA setting				mA
V _{GPIO_IN}	GPIO in high threshold	Percentage of V _{GPIO}	70			%
	GPIO in low threshold	Percentage of V _{GPIO}			30	%
	GPIO in voltage range		0		3.3	V
V _{TX}	TX high voltage	Percentage of V _{GPIO}	70			%
	TX low voltage	Percentage of V _{GPIO}			30	%
	Configurable reset voltage	Percentage of V _{GPIO}	70			%

5.3 **GPIO Connections**

The GPIO connector is an optional galvanically isolated interface to external test equipment such as the testing fixture. The connector consists of one general purpose input and one general purpose output. The output does not supply its own power, it must be externally powered. The type of connector is a 4pin WR-TBL terminal block from Würth Elektronik (691313510004).

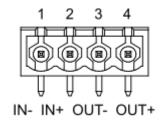


Figure 6. GPIO connector J10

Table 3. GPIO characteristics

Parameter	Description	Min	Typical	Max	Unit
Vouтput	General purpose output voltage		24	80	V
Іоитрит	General purpose output current			5	mA
VINPUT	General purpose input voltage	2		24	V

5.4 Daisy Chaining

The Connectivity PLT allows for up to four Connectivity PLT mainboards to be connected in a chain. Each Connectivity PLT board has a USB in (J17) and a USB out (J18). Each output connects to the next board's input, up to a maximum of four boards, see Figure 7. The USB must be chained from board to board and cannot be connected in any other way (such as through a hub). The power may however be connected as desired, if the requirements mentioned in Section 5.1 are met. Figure 8 shows an example of alternative power connections.

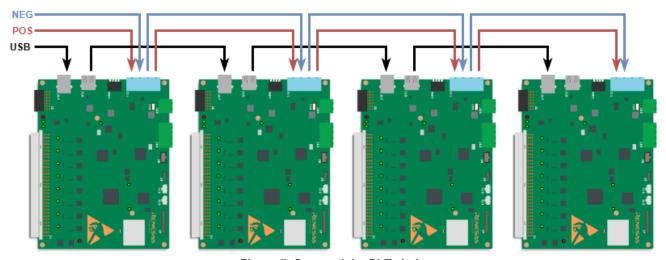


Figure 7. Connectivity PLT chain

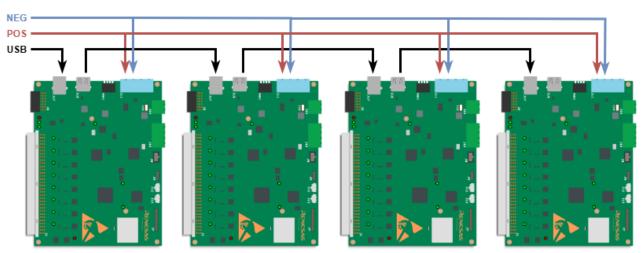


Figure 8. Connectivity PLT chain alternative

5.4.1 Addressing

When using multiple Connectivity PLT boards, the address on each of the boards needs to be set using DIP switches SW1. The switches are numbered, and the ON position is marked on the switch housing. The addressing is in binary format and switch number 1 is the least significant bit. For example, to set board number 3, switches 1 and 2 should be ON, and switches 3 and 4 should be OFF.

5.4.2 Sleep Current Measurement Using External DMM

Using externally connected current measurement equipment on J15, the Connectivity PLT can provide precise sleep current measurements for the DUTs. The current measurement is done on the VDUT rail so all DUT's are measured simultaneously. A jumper on J14 is used to bypass the external current measurement.

To set up the sleep current measurement with an external instrument, jumper J14 must be removed and a connection between J15 and the instrument needs to be made. Two wires from the positive and negative current measurement connections of the DMM must be connected to the terminal block for J15. The instrument must be NI VISA compatible through a USB connection or through a GPIB interface. The implemented protocol is compatible with Agilent/Keysight 3440x common among many DMMs.

The NI VISA drivers and software also need to be installed, see Section 6.4.

5.5 Production Line Setup

To deploy the Connectivity PLT in a production environment, there are some considerations that must be made regarding the RF environment. If any RF tests are to be performed by the Connectivity PLT, there should be minimal background noise and interference. The recommended way to achieve this in any production environment is to place the Connectivity PLT main board(s), DUT's, and RF testing unit in a shielded box. Figure 9 shows a single board and single RFTU setup, and Figure 12. When multiple PLT main boards and multiple RFTUs are used, they can be set up in multiple shieled boxes (Figure 11) or a single shielded box (Figure 12).

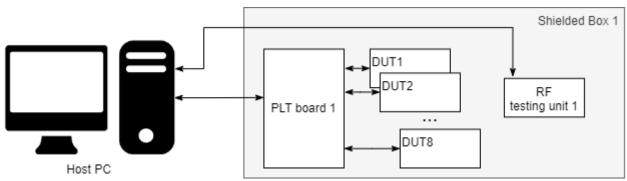


Figure 9. Connectivity PLT in a shielded box

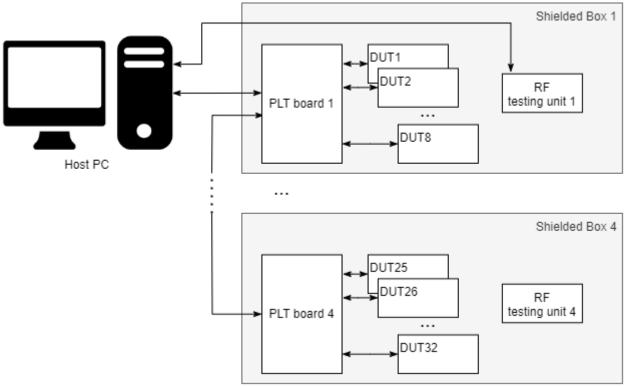


Figure 10. Connectivity PLT chain in multiple shielded boxes

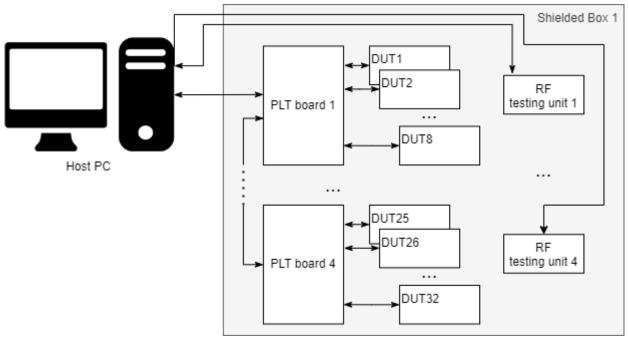


Figure 11. Connectivity PLT chain in single shielded box with multiple RF testing units

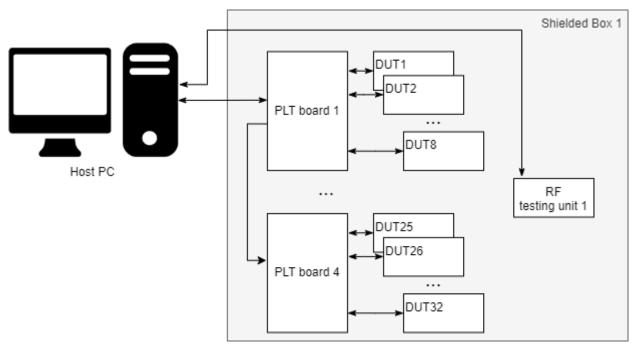


Figure 12. Connectivity PLT chain in single shielded box

6. Installation

6.1 Introduction

This section provides information on how to install the Connectivity PLT software. The Connectivity PLT is not a single application but a group of services and applications that can be installed on a single host or multiple networked machines. The installation process differs depending on the individual setup of the production line.

A single installer is used for all types of installation.

6.2 Architecture and Different Setup Strategies

The Connectivity PLT is split into two services and a few user interface applications, see Figure 13.

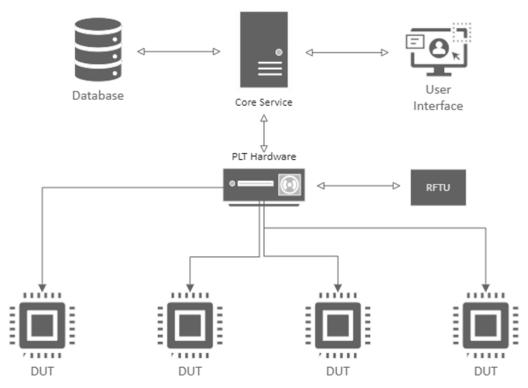


Figure 13. Connectivity PLT Architecture

6.2.1 PLT Services

The Connectivity PLT installer can install two Windows services:

- The Renesas Connectivity PLT Database Service a host service for the main database that holds all the production related data such as serial numbers, BD addresses, test logs and results.
- The Renesas Connectivity PLT Core Service —the main service responsible for executing all operations at the host machine which has a physical connection to the PLT hardware.

These services can either be installed and run as windows services or can be manually started to run in a shell window and can be installed on the same system or on separate networked machines.

6.2.2 PLT Applications

- Connectivity PLT the main application which provides the user interface to the Connectivity PLT execution. This application can run on a separate but networked system to the core service or locally at the same system.
- Connectivity PLT CLI a command line interface with similar functionality to the main application but without
 a graphical user interface. This application can run on a separate but networked system to the core service or
 locally at the same system.

- Connectivity PLT Configuration an application providing a user interface to configure every aspect of the PLT operation, including setup, tests, and programming. This application needs to run on the same system as the core service.
- Connectivity PLT Service Agent a tray application providing access to the Core Service log when it is running as a windows service as well as a simple way to start and stop the windows service. This application needs to run on the same system as the core service.
- Connectivity PLT Firmware Update an application providing an interface to update the Connectivity PLT firmware. This application needs to run on the same system that the hardware is connected to.

6.3 Installation

6.3.1 Standard Installation

To install all applications and services of the Connectivity PLT on a single host system, run the installer with default selections and with the **Install Connectivity PLT CoreService as a Windows Service** checkbox selected.

It is strongly recommended to keep the installation folder in the default location. However, if it is necessary to change it, select a folder that does not require special permissions, for example, user folders or application folders. The windows services are executed from the SYSTEM account that does not have access to users' or some other special folders.

6.3.2 Remote System Installation

Installation of Core Service, Database Service, and Application can be installed on two or three separate remote systems.

■ CoreService System – this should be installed in the system that is physically connected to the Connectivity PLT hardware. The service can be installed by enabling the Renesas Connectivity PLT Core Service windows service checkbox in the installation wizard Figure 14. Take note of the IP address of the system, it is needed for the configuration of the Connectivity PLT application.

☑ Install Connectivity PLT CoreService as a Windows Service

Figure 14. CoreService Windows Service installation

■ Database Service System – to use another host only as the database service, complete the installation enabling the Renesas Connectivity PLT Database Service Windows service during the installation and disabling the CoreService installation (Figure 15). Remember the IP address of this host as well. For the CoreService to communicate with the database on separate host, the configuration should be updated with the correct IP address or host name as shown in Figure 16.

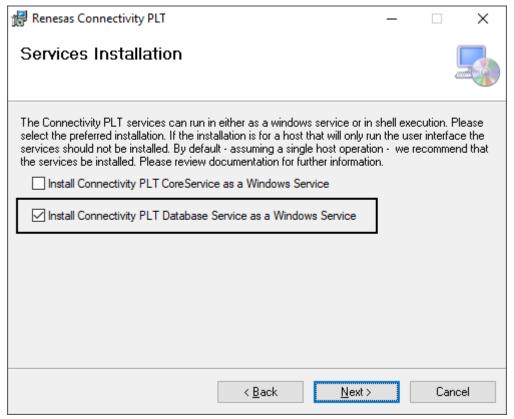


Figure 15. Database Service Installation

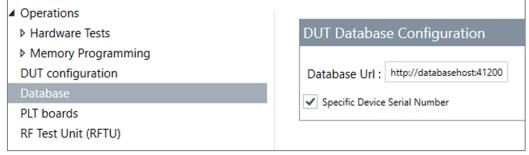


Figure 16. Database Host configuration

Connectivity PLT Application (main application system) – the third system can be used as an operators' console which is, for example, located further away from the hardware. For this instance, during the installation, no services should be selected.

To set up the system in a distributed architecture, the configuration needs to be updated of the main application to use the correct IP address of the CoreService. Go to the C:\Renesas Electronics\Renesas Connectivity PLT\ Renesas_Connectivity_PLT.exe.config file and update the HostUrl value to the correct IP address of the CoreService host as shown in Figure 17.

Figure 17. Main Application CoreService Host configuration

6.4 Install Necessary Drivers

Due to licensing restrictions, some drivers cannot be included in the installation package. You need to manually download and install these drivers.

Segger J-Link driver – can be installed as part of the Segger J-Link Application installation. You can
download the driver from https://www.segger.com/downloads/jlink/.
 If the installer is launched from a restricted account, you need to run the driver installer manually as an
administrator. The driver installer is in the installation folder of the JLink application. (Figure 18).

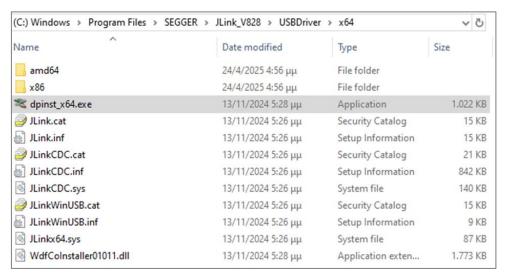


Figure 18. Jlink driver installer

- NI Visa drivers if an external DMM or other instruments are used for tests, then NI Visa drivers are required. You can download the drivers from https://www.ni.com/en/support/downloads/drivers/download.ni-visa.html#558610.
- Microchip SAM-BA driver used for updating the firmware of the connectivity PLT hardware. You can
 download the driver from https://www.microchip.com/en-us/development-tool/sam-ba-in-system-programmer.

6.5 Update and Uninstall

To update to the newest version of the Connectivity PLT, first uninstall the previous version, and then install the needed version.

The pre-generated project files are not removed from the installation folder during the uninstall process. However, remember to keep a backup of the Configuration files, when new configuration files are introduced during the installation the old ones are going to be deleted. Figure 19 shows an example of configuration files and folders that should be backed up.

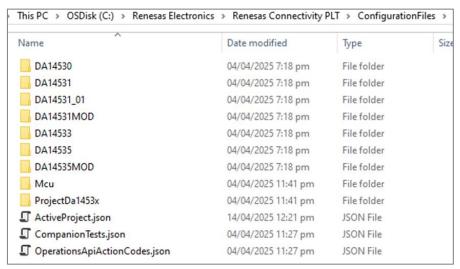


Figure 19. Configuration files

7. Database Service

The Renesas Connectivity PLT Database Service provides access to the database holding the product information as well as other details through a network interface (web service). It is used by the Connectivity PLT to identify serial numbers matched to BD addresses, store information about the test process and results, and retrieve data that is required to be written to the DUTs storage (eFlash, OTP, external Flash, EEprom).

7.1 Installation

Installation of the Renesas Connectivity PLT Database Service, can be achieved using the same Connectivity PLT Installer.

The database service can be installed as a Windows service, using the same Connectivity PLT installer, and run in the background. Alternatively, it can be executed from a shell window with administrator privileges. It can be installed on the same host system as the one that executes the core service or on a remote system, if it is accessible over the network.

It is strongly recommended that it is installed as a service, in which instance no interaction with the user is required to access the database, it automatically starts during power up in the background with the correct privileges.

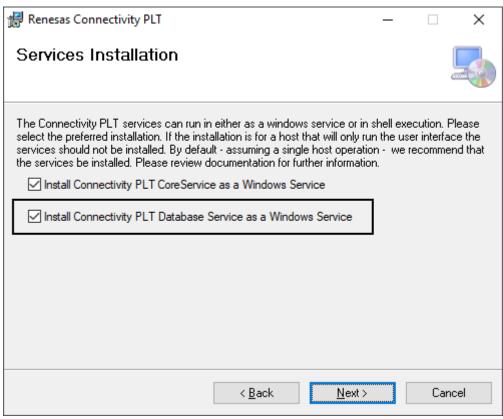


Figure 20. Database Service Installation

By default, the entire Connectivity PLT folder structure is installed on C:\Renesas Electronics\Renesas Connectivity PLT. The database.db file is in the Database folder in the root folder of the installation, and the database service is configured to locate the database at this location.

If you have changed the installation folder or want to move the database to another location, do the following:

- 1. Open the DatabaseService\bin\Renesas_Connectivity_Plt_Database_Service.exe.config file using a text editor.
- 2. Locate the following entry

<connectionStrings>

<add name="DevicesDatabase" providerName="System.Data.SQLite" connectionString="Data
Source=C:\Renesas Electronics\Renesas Connectivity PLT\Database\DevicesDatabase.db; Integrated
Security=True" />

</connectionStrings>

and then change the DataSource property to the correct location of the database file.

3. Save the file and restart the service.

7.2 Database Structure

The database contains a few different tables to hold all the necessary information.

7.2.1 Devices Table

The Devices table is the main table storing the list of serial numbers and corresponding BD addresses. After the installation, the database already contains some data for testing and demonstration purposes. Before going into production, you need to replace this data with the serial numbers and board addresses range based on your specific needs.

To manage the database directly, use SQLite tool (https://sqlitebrowser.org/).

Figure 21 shows the database devices table structure in the SQLite tool.

Devices		CREATE TABLE "Devices" ("SerialNumber" TEXT		
SerialNumber	TEXT	"SerialNumber" TEXT NOT NULL UNIQUE		
BluetoothLowEnergyAddress	INTEGER	"BluetoothLowEnergyAddress" INTEGER UNIQUE		
BluetoothClassicAddress	INTEGER	"BluetoothClassicAddress" INTEGER UNIQUE		
WiFiMacAddress	INTEGER	"WiFiMacAddress" INTEGER UNIQUE		
AccessCount	INTEGER	"AccessCount" INTEGER NOT NULL		
Timestamp	INTEGER	"Timestamp" INTEGER		
Result	INTEGER	"Result" INTEGER NOT NULL		

Figure 21. Database Devices table structure

- Serial Number text field, must contain text representing the serial number, it must be unique, is the index
- BluetoothLowEnergyAddress integer field, contains the entire Bluetooth LE address as a 64-bit integer
- BluetoothClassAddress integer field, contains the entire Bluetooth Classic address as a 64bit integer. (only used in devices that support classic Bluetooth)
- WiFiMacAddress integer filed, contains the entire MAC address as a 64-bit integer (only used in devices that support Wi-Fi).
- AccessCount integer filed, contains a counter signifying how many times this entry is accessed by the Connectivity PLT
- Timestamp integer field, a timestamp of the last access represented in unix timestamp format
- Result integer filed, represents the results of the last test run on the Connectivity PLT.

7.2.2 Device Access Logs Table

The DeviceAccessLogs table holds information about every time the Connectivity PLT has accessed each device entry based on the serial number (index). This table should not be changed by any external processes or manually.

Figure 22 shows the Device Access Logs table structure in the SQLite tool.

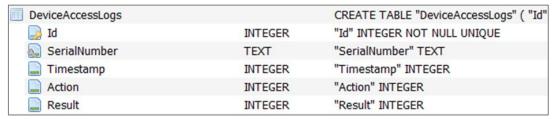


Figure 22. Database Device Access Logs table structure

- Id integer field, a unique ID of the entry (index)
- SerialNumber text field, Reference to the Devices Table of the entry
- Timestamp integer field, a timestamp at the time of access represented in unix timestamp format
- Action integer field, an enumeration of the Connectivity PLT action log entry.
- Result integer field, the result of the action.

7.2.3 Custom Memory Data Table

The CustomMemoryData table contains data to be stored on the DUT tied to a specific serial number. This can be useful, for example, to store the serial number and other information that is unique to each device. For every continuous sequence of data a new entry should be made, multiple entries can exist for each serial number, each entry is programmed at the specified memory type and address specified. The write process is enabled during the configuration of the testing.

Figure 23 shows the Custom Memory Data table structure in the SQLite tool.

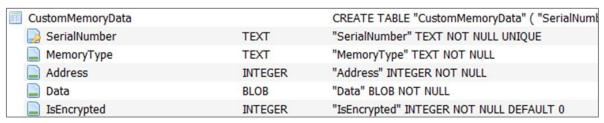


Figure 23. Database Custom Memory data table

- SerialNumber text, Reference to the Devices Table of the entry
- Memory Type text, specifies the type of memory that the data should be stored at
 - SpiFlash
 - Otp
- Address integer, the memory address at which the data should begin to be stored
- Data blob, the data stored in binary format.
- IsEncrypted integer, specifies if the data entry is encrypted (1) or not (0).

Example of storing:

- Data of a random 32 bit number at adress 0x10000 of the SPI Flash
- and the serial number at address 0x200000.

Entry 1

SerialNumber: 0x12345678MemoryType: SpiFlashAddress: 0x10000

Data: [random number in binary blob]

IsEncrypted: 0

Entry 2

SerialNumber: 0x12345678MemoryType: SpiFlashAddress: 0x200000

Data: [serial number in binary blob]

■ IsEncrypted: 0

Another example of a different binary file loaded to the OTP for each serial number:

SerialNumber: 0x12345678

MemoryType: OtpAddress: 0x1000Data: [0x12345678.bin]

■ IsEncrypted: 0

7.2.4 Common Memory Data Table

The CommonMemoryData table contains data to be stored on every DUT. This can be useful for storing data for all the devices regardless of their serial number. For every continuous sequence of data a new entry should be made, each entry is programmed at the specified memory type and address specified. The write process is enabled during the configuration of the testing.

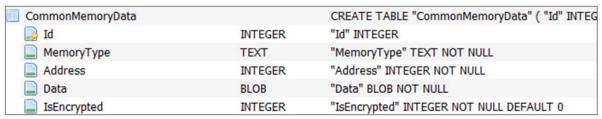


Figure 24. Database Common Memory Data table structure

- Memory Type Text, specifies the type of memory that the data should be stored at
 - SpiFlash
 - OTP
- Address Integer, the memory address at which the data should begin to be stored
- Data Blob, the data stored in binary format.
- IsEncrypted Integer, specifies if the data entry is encrypted (1) or not (0).

Example of setting that is common on all devices stored in SPI flash:

MemoryType: SpiFlashAddress: 0x10000

Data: [0x01 0x02 0x03 0x04]

■ IsEncrypted: 0

7.3 Data Encryption

A basic encryption method is implemented for the data stored in the database. The data should be encrypted before storing them into the database.

The encryption method is AES on a 256-bit key.

The key for decryption is stored in C:\Renesas Electronics\Renesas Connectivity PLT\DatabaseService\bin\ Renesas Connectivity Plt Database Service.exe.config.

In the appSettings section, entry: <add key="decryptionKey" value="1234567" />

This should be changed to the key used for the encryption for the PLT to be able to decrypt and store the data.

8. Connectivity PLT Configuration

The Renesas Connectivity PLT Configuration is used to set up the system according to the device hardware options and select the required tests and memory actions to be performed.

The Connectivity PLT Configuration application (Renesas_Connectivity_PLT_Configuration.exe) is an application, which is used to appropriately configure the tests and memory operations the tool performs. Depending on the selected device chipset and the enabled actions, only appropriate options are enabled and shown. Any change made is validated before being saved to the JSON file. This prevents erroneous values from being stored in the JSON file that would harm the production procedure.

8.1 Connectivity PLT Configuration Window

The tree list in the side navigation is automatically created based on the folder structure in ConfigurationFiles folder in the application folder. Folders become parent items, and the contents (JSON configuration files) become child items. Clicking on a tree item either expands the contents of the folder or displays the configuration parameters of the file. If there is an error in any of the configuration JSON files, a warning message is shown indicating which of the parameters has an error.

Figure 25 shows the initial Connectivity PLT Configuration window with the first configuration item in the tree menu on the left.

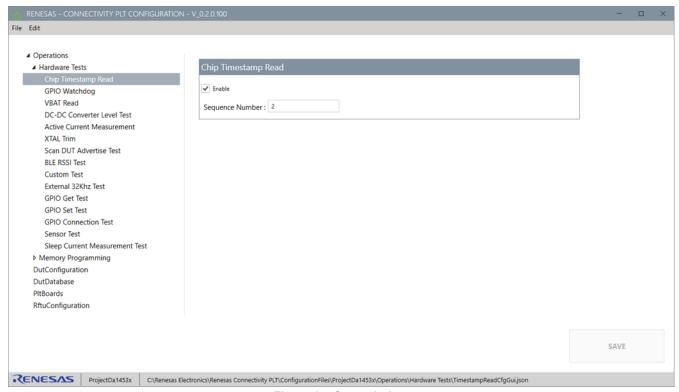


Figure 25. Start window

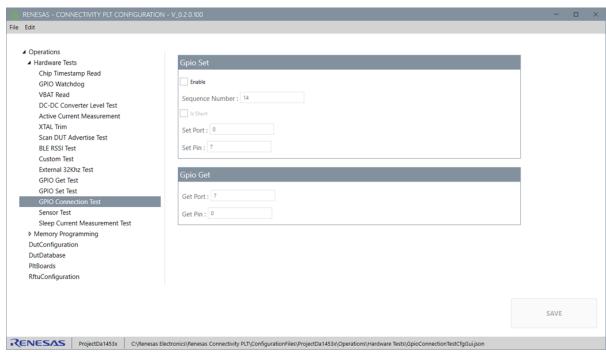


Figure 26. Tree menu

You can use menu options to manage projects: create new ones, open, save, reload or edit.

At the bottom of the window, you can see the location path of the current selected JSON configuration file.

The save button is disabled on startup. After you make a change in any field in JSON configuration files, the save button turns red with an asterisk and the option to save the changes is available. An asterisk also appears on title bar and on windows taskbar. You must save your changes before opening another file.

The parameter fields have a tooltip describing the field and the expected values.

All the parameter fields are protected by regex validation customized to the contents of each field. If an unsupported value or character is inserted, the field turns red and the save button is disabled again until a valid value is entered, Figure 27.

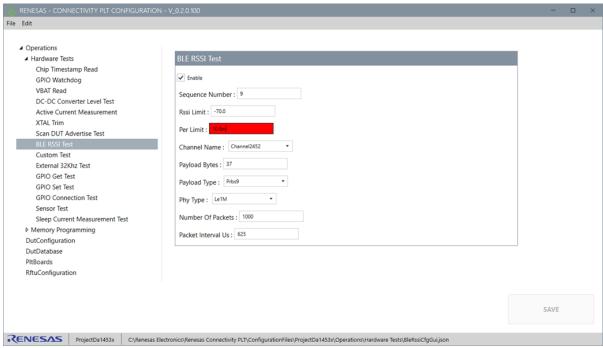


Figure 27. Input error

8.2 Configurations

8.2.1 Project Configuration

You can save information into projects to easily switch between different test procedures or devices in the Connectivity PLT. Each project is a set of configuration files stored in a separate folder named as the project. By default, when Connectivity PLT is installed, a few projects representing different ICs are created automatically.

To create a new project configuration, go to **File> Create New Project**. In the **Create New Project** dialog, select a base project that is used as a starting point, and add project name. All the necessary files are copied to the new project folder under ConfigurationFiles folder and side navigation refreshes displaying the new project.

8.2.2 Database Configuration

Database configuration is used to store serial numbers, Bluetooth LE addresses, BT classic addresses, Wi-Fi mac addresses; information used in testing, such as common memory data and custom memory data, and statistics like passed/failed tests, access count, timestamps. If the Connectivity PLT Database Service is installed on a separate machine you need to set the correct URL and port to point to this machine.

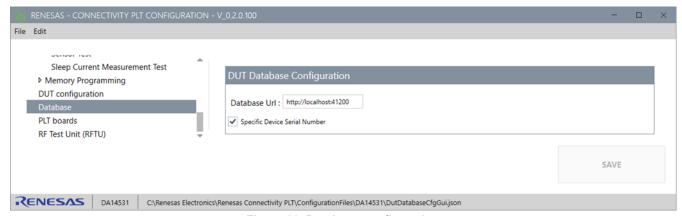


Figure 28. Database configuration

The Connectivity PLT used the database to assign BD addresses based on serial numbers previously entered in the database. The option to have Specific Device Serial Number enables a dialog to appear at the beginning of the test procedure to enter the serial number of the first DUT. This is usually done using a barcode scanner. For more details, see Section 7.

8.2.3 PLT Boards Configuration

The Connectivity PLT boards configuration has four available Connectivity PLT boards, and you can enable them and assign a location in the chain, see Figure 29. For each Connectivity PLT board, there are eight available test positions. For the minimum configuration, you must enable at least one Connectivity PLT board and one DUT.

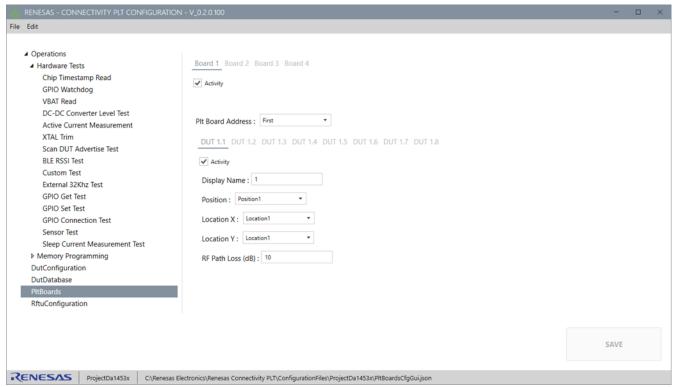


Figure 29. PltBoards configuration

Table 4. PltBoards parameters

Parameter	Description					
PLT Board	PLT Board					
Activity	Enables or disables the usage of the specific PLT Board.					
PLT Board Number	Sets the PLT Board number (Zero, First, Second, Third).					
PLT Board Address	Sets the address of the PLT Board (First, Second, Third, Fourth).					
DUT						
Activity	Enables or disables the usage of the specific DUT.					
Display Name	The name of each DUT in the testing environment.					
Position	The position of each DUT on the PLT Board.					
Location X	The location of each DUT, in X axis, in the testing environment grid.					
Location Y	The location of each DUT, in Y axis, in the testing environment grid.					
RF Path Loss (db)	The value to be used in RF Path Loss, in dBm.					

Location X/Y adjusts the view of the DUT tiles in the testing environment to simulate the actual hardware layout. Each DUT can be placed wherever needed in the Execution GUI grid. Figure 30 and Figure 31 show examples of two different views on the testing environment by adjusting Position X and Position Y.

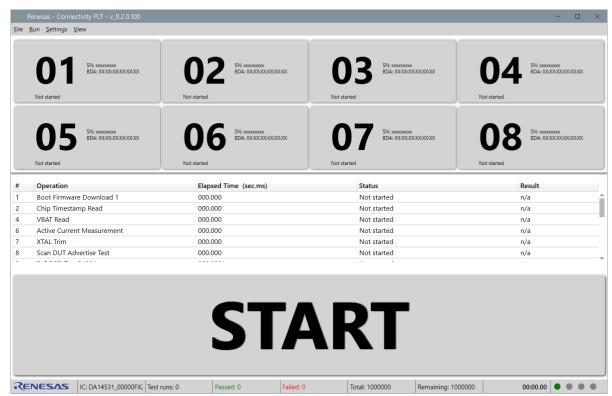


Figure 30. Default tile configuration

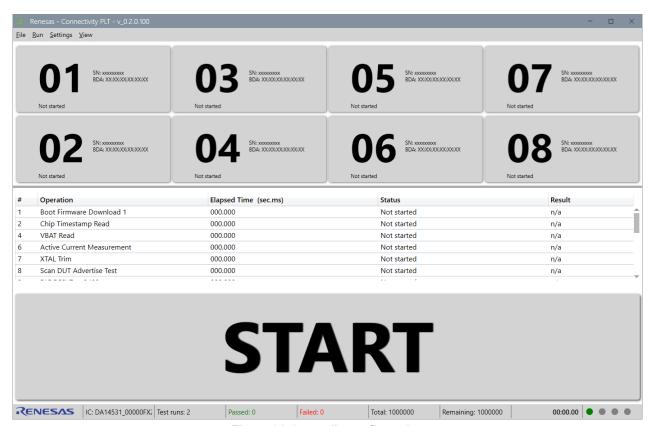


Figure 31. 2-row tile configuration

8.2.4 RFTU Bluetooth LE Configuration

The Connectivity PLT system can be configured to use one or multiple RFTUs. Multiple RTFUs can be used for cases when the multiple boards exist on the chain and are separated by distance or other RF blocking methods.

Different RFTU configurations are available. At a minimum one RFTU is necessary when RF tests are going to be performed during the test process. Figure 32 demonstrates the default and minimum RFTU configuration. The communications Interface name be se set to empty to be automatically detected.

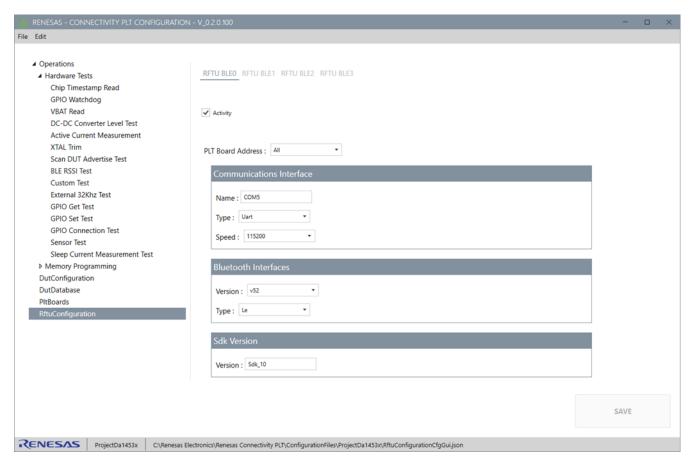


Figure 32. RFTU Bluetooth LE configuration

Table 5. RFTU configurations options

Option	Description					
RFTU BLE	FTU BLE					
Activity	Enables or disables the usage of the specific RFTU.					
Number	RFTU number starting from 0 (first, second, third, fourth).					
Plt Board Address	All if the specific RFTU is used for all PLT boards.					
	Otherwise, the address (through the DIP switches) of the associated PLT board to be tested with the specific RFTU (first, second, third, fourth).					
Communications Inte	rface					
Name	Assigns a name to the communications interface.					
Type Defines the specific interface (UART, SingleWireUART, SPI, JTAG, SWD)						
Speed Defines speed of the communication interface, for example 115200.						
Bluetooth Interfaces						
Version	Version of the Bluetooth interface (v40, v41, v42, v50, v51, v52, v53)					
Туре	Type of the Bluetooth interface (Classic, LE).					
Sdk Version	Sdk Version					
Version	The version of the SDK used.					

8.2.5 DUT Configuration

The DUT Configuration section is dedicated to parameters specific to the actual devices that are under test. There are numerous parameters to describe the hardware properties, communication interfaces and so on.

8.2.5.1 DUT Configuration – Device IC

The Device IC under Dut Name is the generic type of the IC used.



Figure 33. Dut configuration

8.2.5.2 MCU Configuration

The MCU configuration section sets all the parameters specific to the MCU being used by the DUT.

Mcu Name – the exact part number of the MCU used for the DUT.

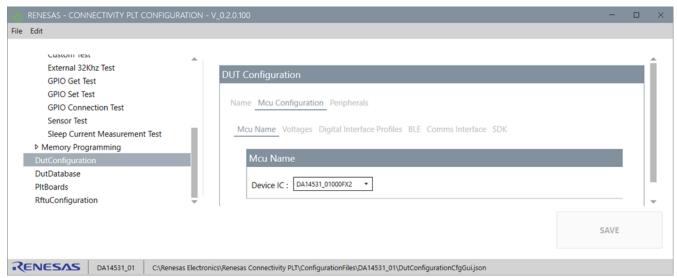


Figure 34. MCU name configuration

- Voltages
 - Vbat is the voltage that the Connectivity PLT board supplies to the DUT.
 - Vddio is the voltage of the digital interface.

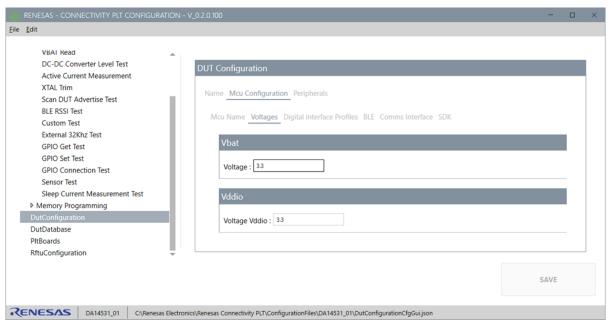


Figure 35. Voltages configuration

- Digital Interface Profiles
 - **SpiProfile** groups a set of parameters for the SPI interface commonly used for flash memory and sensors. This is a primary configuration of the interface that is used if no further profile is defined for the specific peripheral.

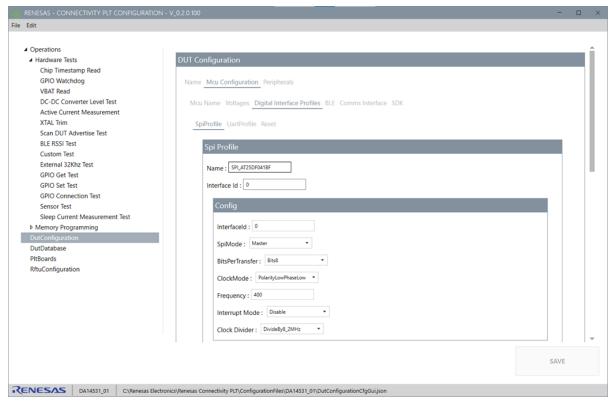


Figure 36. SpiProfile configuration

Table 6. SPI profile options

Option	Description
Config	

Option	Description
InterfaceId	The ID of the interface used
BitsPerTransfer	Bits8, Bits16
ClockMode	PolarityLowPhaseLow, PolarityLowPhaseHigh, PolarityHighPhaseLow, PolarityHighPhaseHigh
Frequency	For example, 400
Interrupt Mode	Enable/Disable
Clock Divider	DivideBy8_2MHz, DivideBy4_4MHz, DivideBy2_8MHz, DivideBy14_16MHz

Table 7. SPI profile pin options

Option	Description		
Miso	Miso		
Port	MISO GPIO port		
Pin	MISO GPIO pin		
Mosi			
Port	MOSI GPIO port		
Pin	MOSI GPIO pin		
Sclk			
Port	SCLK GPIO port		
Pin	SCLK GPIO pin		
Cs			
Port	CS GPIO port		
Pin	CS GPIO pin		

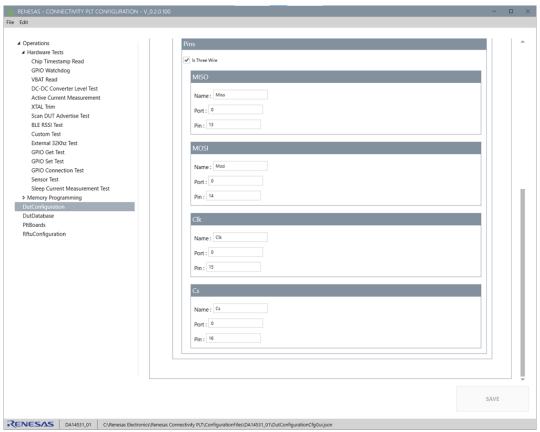


Figure 37. Pin configuration

• UART Profile (Figure 38)

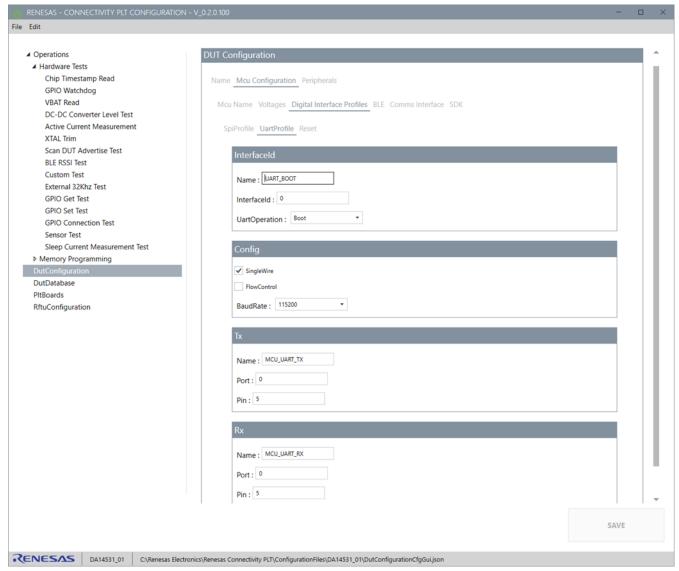


Figure 38. UART profile configuration

Table 8. UART options

Option	Description
Name	The name of the interface
InterfaceId	The id of the interface used
UartOperation	(Boot, Peripheral, Debug)
Single Wire	-
Flow Control	-
Baud Rate	(1200, 2400, 4800, 9600,19200, 38400, 57600, 76800, 115200, 230400, 460800, 576000, 921600, 1M, 2M, 3M, 4M, 5M, 6M)
Name	MCU_UART_TX
Port	Tx Gpio port
Pin	Tx Gpio pin
Name	MCU_UART_RX
Port	Rx Gpio port
Pin	Rx Gpio pin

Reset

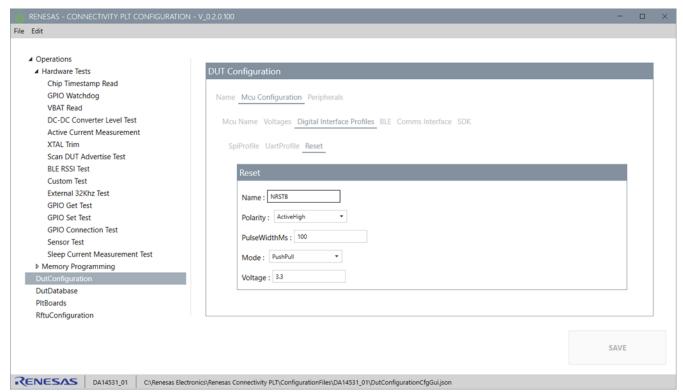


Figure 39. Reset configuration

Table 9. Reset options

Option	Description	
Config		
Name	NRSTB	
Polarity	ActiveHigh, ActiveLow	
Pulse Width Ms	100	
Mode	PushPull, OpenDrain	
Voltage	3.3	

Bluetooth LE

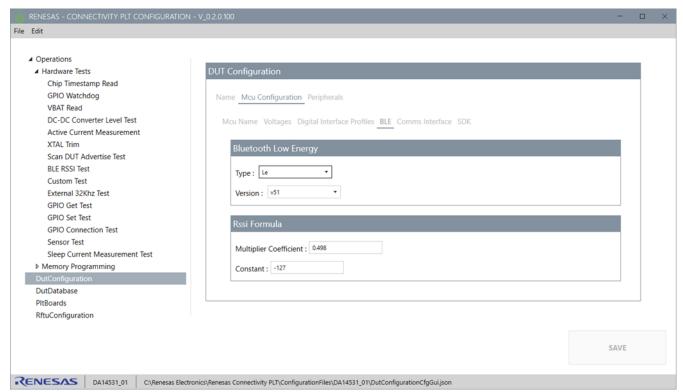


Figure 40. Bluetooth LE configuration

Table 10. Bluetooth LE options

Option	Description		
Bluetooth Low Energy			
Туре	Type of the Bluetooth Interface (Classic, Le)		
Version	Version of the Bluetooth interface (v40, v41, v42, v50, v51, v52, v53)		
Rssi Formula			
Multiplier Coefficient	The coefficient used in the calculation of the RSSI (Conversion factor)		
Constant	The constant used in the calculation of the RSSI (Noise floor)		

■ Comms Interface (Figure 41)

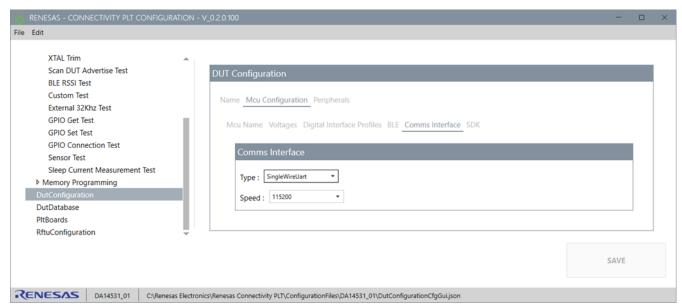


Figure 41. Comms interface configuration

Table 11. Comms interface options

Option	Description	
Config		
Туре	Uart, SingleWireUart, Spi, Jtag, Swd, Usb	
Baud Rate	(1200, 2400, 4800, 9600,19200, 38400, 57600, 76800, 115200, 230400, 460800, 576000, 921600, 1M, 2M, 3M, 4M, 5M, 6M)	

SDK

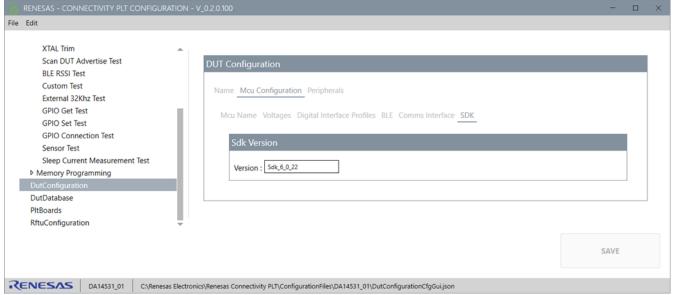


Figure 42. SDK configuration

Table 12. SDK version

Option	Description	
Sdk Version		
Version	The SDK version	

8.2.5.3 Peripherals

Memory

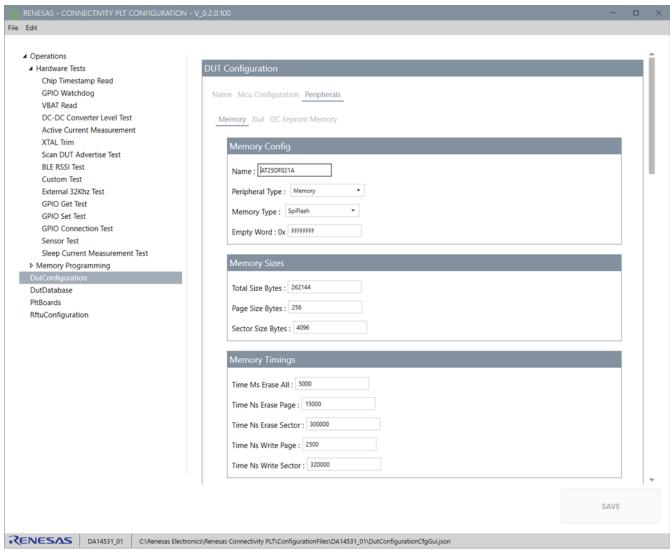


Figure 43. Memory configuration 1

Table 13. Memory configuration

Option	Description		
Memory Config			
Name	The name of the configuration		
Peripheral Type	(Memory, Sensor, Antenna, Led, Button, Switch, Ftdi, Fpga, Dac, Adc, UsbHub, I2cGeneric, SpiGeneric, AddressSwitch, VoltageController, DutController, Nex74CB3Q3253, Ammeter, Xtal)		
Memory Type	(SpiFlash, QspiFlash, OspiFlash, I2cEeprom, Otp, EmbeddedFlash, Rom, SpiEeprom)		
Empty Word	Content of empty flash: 0xFFFFFFF		
Option	Description		
Memory Sizes			
Total Size Bytes	Total memory size in bytes		
Page Size bytes	Page size in Bytes		
Sector Size Bytes	Sector size in Bytes		

Option	Description	
Option	Description	
Memory Timings		
Time Ms Erase All	Time to erase all (chip erase) in milliseconds	
Time Ns Erase Page	Time to erase a single page in nanoseconds	
Time Ns Erase Sector	Time to erase a single sector in nanoseconds	
Time Ns Write Page	Minimum time to write a single page in nanoseconds	
Time Ns Write Sector Minimum time to write a single sector in nanoseconds		

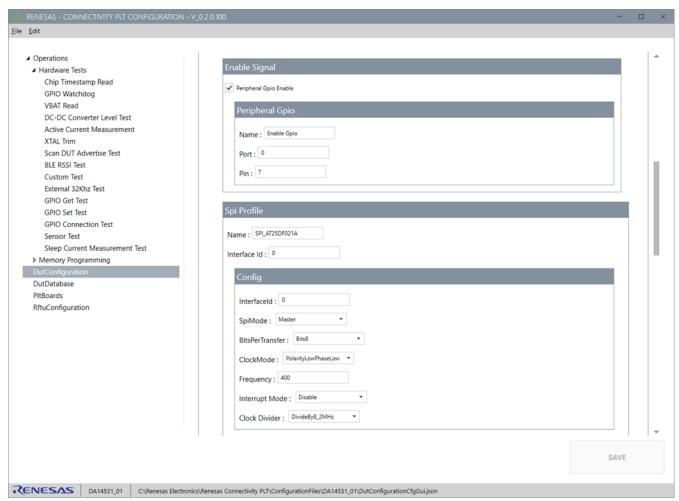


Figure 44. Memory configuration

Table 14. Peripheral GPIO

Option	Description	
Enable Signal		
Peripheral GPIO Enable	Enable the peripheral GPIO	
Name	Name of Peripheral GPIO	
Port	GPIO Port	
Pin	GPIO Pin	

Table 15. SPI profile

Option	Description	
Spi Profile		
Name	Name of SPI profile	
Interface Id	Interface Id	
Option	Description	
Config		
Interface Id	Interface Id	
Bits Per Transfer	(Bits8, Bits16)	
Clock Mode	(PolarityLowPhaseLow, PolarityLowPhaseHigh, PolarityHighPhaseLow, PolarityHighPhaseHigh)	
Frequency	Frequency	
Interrupt Mode	Enable or disable Interrupt Mode (Enable, Disable)	
Clock Divider	(DivideBy8_2MHz, DivideBy4_4MHz, DivideBy2_8MHz, DivideBy14_16MHz)	

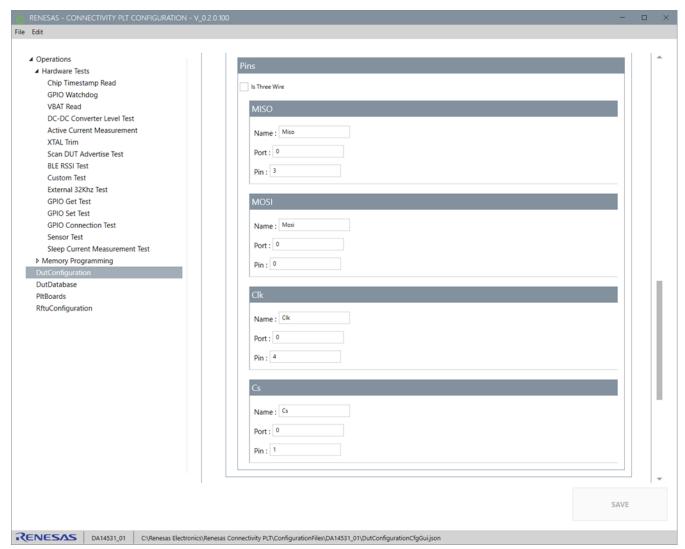


Figure 45. Pins configuration

Table 16. Pins configuration

Option	Description	
Is Three Wire	Enable three wire communication	
Miso		
Name	Name of Miso configuration	
Port	Miso GPIO port	
Pin	Miso GPIO pin	
Mosi		
Name	Name of Mosi configuration	
Port	Mosi GPIO port	
Pin	Mosi GPIO pin	
Sclk		
Name	Name of SCLK configuration	
Port	SCLK GPIO port	
Pin	SCLK GPIO pin	
Cs		
Name	Name of Cs configuration	
Port	Cs GPIO port	
Pin	Cs GPIO pin	

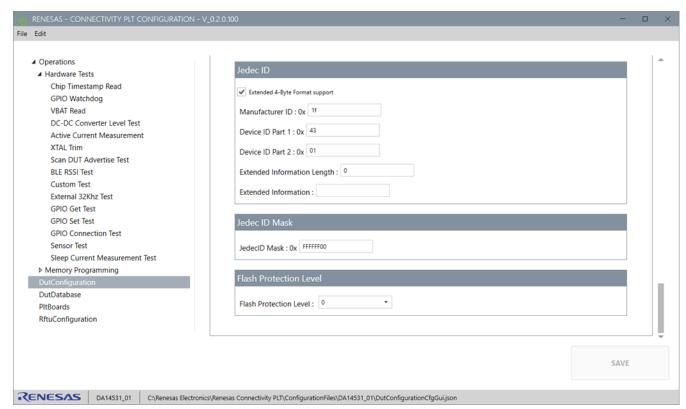


Figure 46. Memory configuration

Table 17. Jedec configuration

Option	Description	
Jedec ID	Jedec ID	
Extended 4-byte For Support	mat	Enable/Disable 4-byte format support
Manufacturer ID		Part of Jedec ID
Device ID Part1		Part of Jedec ID
Device ID Part2		Part of Jedec ID
Extended Information Length		Number of bytes of extended information
Extended Information		Jedec Id extended information
Jedec ID Mask		
Jedec ID Mask		Jedec Id mask to ignore bytes
Flash Protection Level		
Flash Protection Level		(0-15)

Xtal

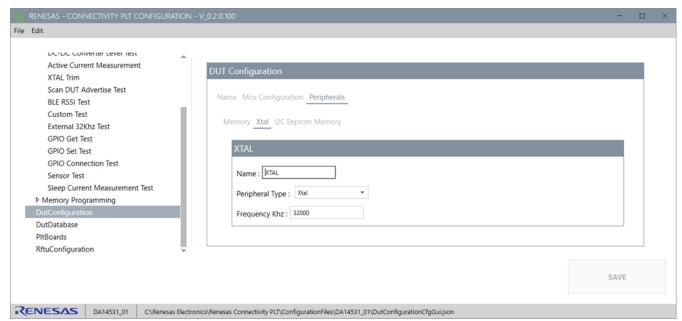


Figure 47. Xtal configuration

Table 18. XTAL configuration

Option	Description
XTAL	
Name	Name of Xtal
Peripheral Type	(Memory, Sensor, Antenna, Led, Button, Switch, Ftdi, Fpga, Dac, Adc, UsbHub, I2cGeneric, SpiGeneric, AddressSwitch, VoltageController, DutController, Nex74CB3Q3253, Ammeter, Xtal)
Frequency kHz	XTAL Frequency in kHz

■ I2C EEPROM Memory

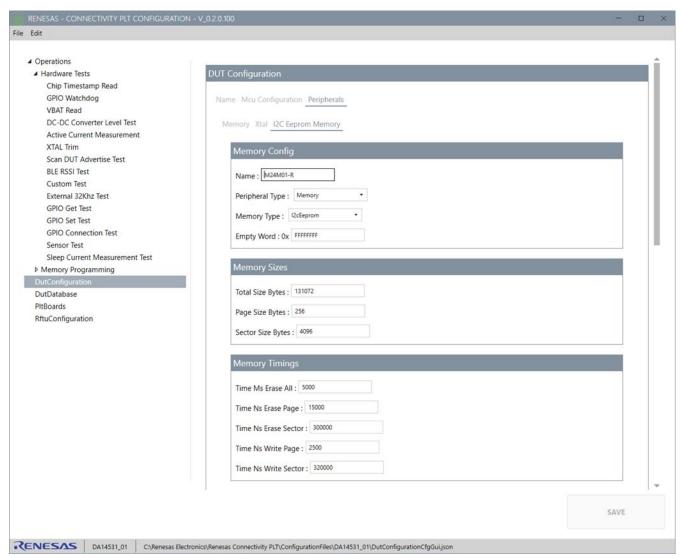


Figure 48. I2C EEPROM configuration 1

Table 19. I2C configuration

Option	Description	
Memory Config		
Name	Name of memory configuration	
Peripheral Type	(Memory, Sensor, Antenna, Led, Button, Switch, Ftdi, Fpga, Dac, Adc, UsbHub, I2cGeneric, SpiGeneric, AddressSwitch, VoltageController, DutController, Nex74CB3Q3253, Ammeter, Xtal)	
Memory Type	(SpiFlash, QspiFlash, OspiFlash, I2cEeprom, Otp, EmbeddedFlash, Rom, SpiEeprom)	
Empty Word	Content of empty eeprom: 0xFFFFFFF	

Table 20. I2C size

Option	Description	
Memory Sizes		
Total Size Bytes	Memory total size in Bytes	
Page Size bytes	Memory page size in Bytes	
Sector Size Bytes	Memory sector size in Bytes	

Table 21. I2C timings

Option	Description
Memory Timings	
Time Ms Erase All	Time to erase all (chip erase) in milliseconds
Time Ns Erase Page	Time to erase a single page in nanoseconds
Time Ns Erase Sector	Time to erase a single sector in nanoseconds
Time Ns Write Page	Minimum time to write a single page in nanoseconds
Time Ns Write Sector	Minimum time to write a single sector in nanoseconds

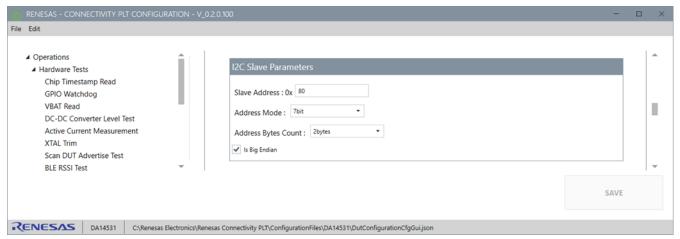


Figure 49. I2C slave parameters

Table 22. I2C slave configuration

Option	Description
I2C Slave Parameters	
Slave Address	Slave address in hex
Address Mode	(7bit, 10bit)
Address Byte Count	(1byte, 2bytes, 3bytes)
Is Big Endian	Set if Big Endian

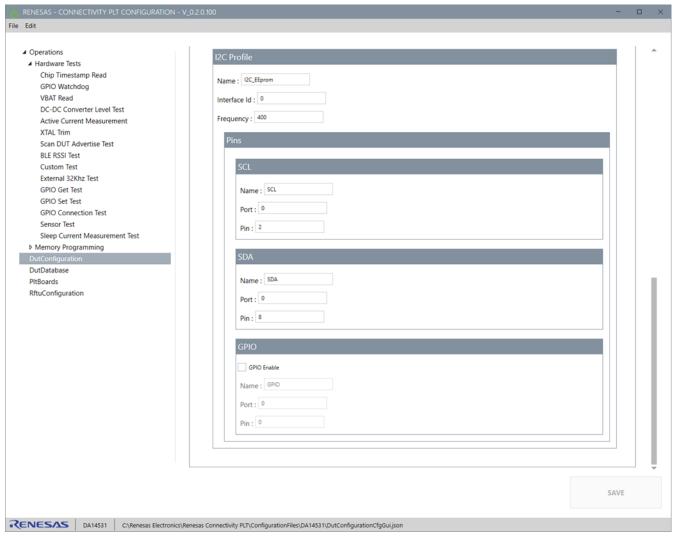


Figure 50. I2C profile

Table 23. I2C profile configuration

Option	Description
I2C Profile	
Name	Profile name
Interface Id	Interface Id
Frequency	Profile frequency

Table 24. I2C pins configuration

Option	Description		
SCL	SCL		
Name	SCL name		
Port	Scl Gpio port		
Pin	Scl Gpio pin		
SDA	SDA		
Name	SDA name		
Port	Sda Gpio port		
Pin	Sda Gpio pin		

Option	Description	
GPIO	GPIO	
Gpio Enable	Enable Gpio	
Name	Gpio name	
Port	Gpio port	
Pin	Gpio pin	

8.2.6 Configure Sequence Number

A sequence number is assigned to every test and represents the order in which the tests are executed. The order is reflected in the side navigation panel. You can edit the sequence number.

If the sequence number is duplicated, an error message is displayed informing that the specific sequence number is in use and the test name that uses it, Figure 51.

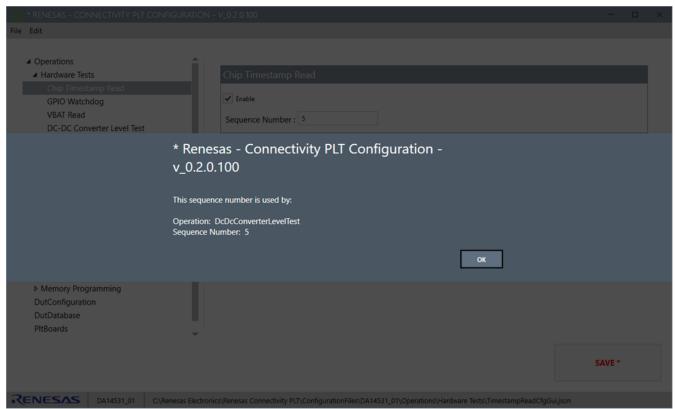


Figure 51. Sequence number configuration

8.3 Hardware Tests Configurations

This section groups all the tests that are not related to memory programming, see Table 25. Typically, each test represents a hardware function and has defined pass and fail criteria.

Table 25. Type of hardware tests

Operation type	Description
Chip Timestamp Read	Not an actual test but is used mainly to log the information that was stored in the CS area of the OTP during factory programming. See Section 8.3.1.
GPIO Watchdog	Enables a periodic pulse at a specific CPU pin that can be utilized by the specific product as an external watchdog monitor. See Section 8.3.2.
VBAT Read	Sends a command to the DUTs to measure their VBAT using their internal ADC. See Section 8.3.3.

Operation type	Description
DC-DC Converter Level Test	Used to measure the output of the on-board DC-DC converter. See Section 8.3.4.
	A lower and upper limit are used to define the pass/fail criteria.
Active Current Measurement	Measures the current consumed by the DUT at this stage of testing. In most cases this is the current consumption of the entire product. See Section 8.3.5.
XTAL Trim	Calculates the correct crystal oscillator trim value. The trim value of the crystal is important to achieve accurate frequency of the Bluetooth LE radio. See Section 8.3.6.
Scan Dut Advertise	Tests the transmission of Bluetooth LE advertising packets for each DUT. See Section 8.3.7.
Bluetooth LE RSSI Test	Tests the reception of Bluetooth LE signals by the DUTs. See Section 8.3.8.
Custom Test	Used for vendor specific operations. These tests are developed within the production test firmware and follow a specific format. The tests are initiated by a single byte HCl command and report back a byte indicating the status of the test. See Section 8.3.9.
External 32 kHz Test	Checks if the 32 kHz crystal is present and operated correctly. See Section 8.3.10.
GPIO Get Test	Evaluates the state of a specific pin. This test is commonly used to check interoperability between other devices and the CPU in the customers' product; and can also be used to check for short circuit between pins. See Section 8.3.11.
GPIO Set Test	Sets a CPU pin to a specific state. It is commonly used for interoperability between other devices and the CPU in the customers' product; and can also be used to check for short circuit between pins in conjunction with a GPIO get Test. See Section 8.3.12.
GPIO Connection Test	Combines set and get GPIO operations to check connectivity between CPU pins. See Section 8.3.13.
Sensor Test	Tests interoperability between the CPU and attached sensors to the I2C or SPI bus. See Section 8.3.14.
Sleep Current Measurement Test	Measures the current consumption of the DUTs during sleep mode. Due to the extremely low currents, an external DMM instrument is required for this operation to make very accurate measurements. The measurement is performed on the VDUT power supply of the Connectivity PLT and is cumulative of the current from all DUTs. The result is divided by the number of active DUTs, report and compared to pass/fail criteria. See Section 8.3.15.

8.3.1 Chip Timestamp Read

It can be useful for traceability and quality control.



Figure 52. Chip timestamp configuration

8.3.2 GPIO Watchdog

The pin output toggles throughout the entire test process with the exception of the firmware download process. Following the firmware download process the watchdog output resumes.

The pulse on the GPIO has approximately 0.75% duty cycle and 0.5 Hz frequency.



Figure 53. GPIO watchdog configuration

8.3.3 VBAT Read

This is a very useful tool to verify the operation and accuracy of the internal ADC. The VBAT level is further logged for traceability or any other purpose.



Figure 54. VBAT read configuration

8.3.4 DC-DC Converter Level Test

This is a useful test to check the operation of this function of the MCU and log its operating characteristics. A lower and upper limit are used to define the pass/fail criteria.

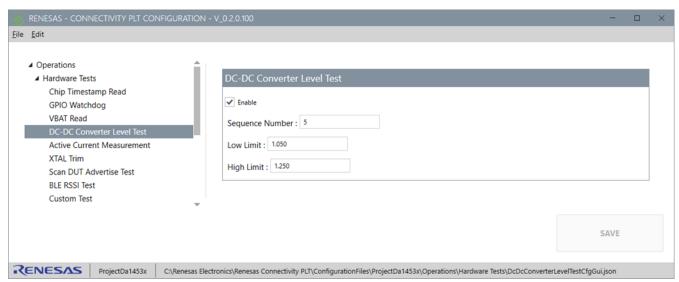


Figure 55. DC-DC converter configuration

8.3.5 Active Current Measurement

This is an extremely useful diagnostic test as the current consumption can be a significant indicator of the DUT product. An upper and lower limit are used to define the pass/fail criteria.

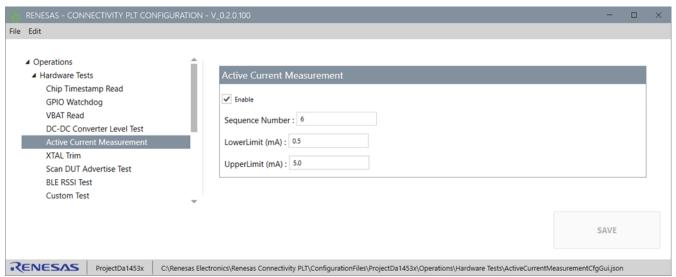


Figure 56. Active current measurement configuration

8.3.6 XTAL Trim

It is recommended that all devices with RF radio go through the trim process to maintain their frequency offset to minim PPM deviation. The XTAL trim process is completed using a combination of the Connectivity PLT Hardware clock signal and an internal calibration method of the DUT. For this process, a pin of the MCU is used to receive the calibration pulse. By default, configuration this pin is the UART RX pin.



Figure 57. XTAL configuration

8.3.7 Scan Dut Advertise

This is a core test of the RF functionality of DUT. All DUTs are set in Bluetooth LE advertising mode through standard HCl commands whilst the RFTU is set in reception mode looking to capture all the BD addresses that are advertising. During the initiation of the test temporary BD addresses are issued for the DUTs, these addresses are then compared to the received ones. The pass/fail criterial is the actual reception of the advertising packet and the RSSI (signal strength) of it.

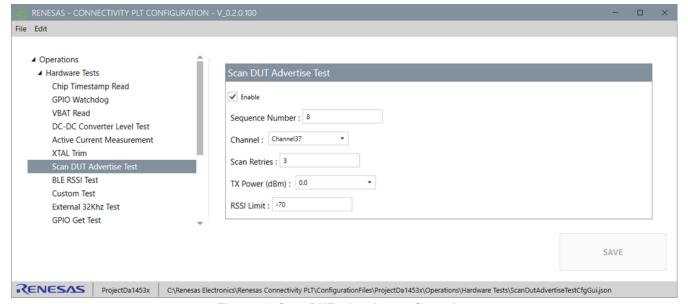


Figure 58. Scan DUT advertise configuration

8.3.8 Bluetooth LE RSSI Test

A set of packets is transmitted by the RTFU using the specified settings and received by all the DUTs. The metrics of the received packets are used to determine if the reception is within the acceptable range. The set metrics tested are the average RSSI and the total PER.

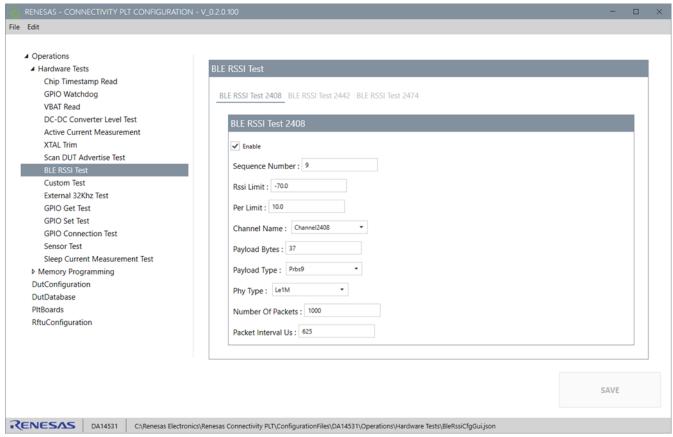


Figure 59. Bluetooth LE RSSI configuration

The RSSI Limit is the lowest acceptable level for the DUT to pass the test. The result is calculated by averaging the RSSI measurement of all packets.

The PER Limit if the highest acceptable level for the DUT to pass the test The result is calculated by the total packet errors.

8.3.9 Custom Test

The tests are commonly used for extended sensor test procedures that require more than a single read-write operation. By default, a return value same as the command value indicates a pass status.

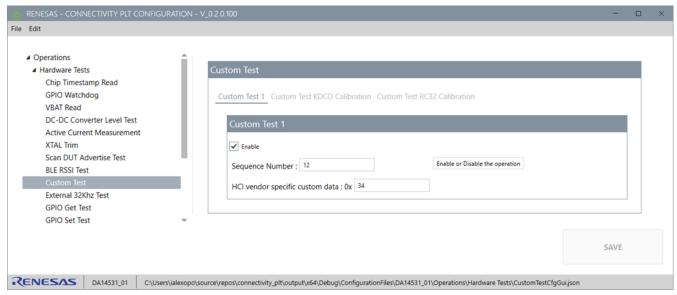


Figure 60. Custom test configuration

8.3.10 External 32-kHz Test

Its frequency is measured against the main clock source of the DUT. This test is only applicable on devices that support secondary oscillators.

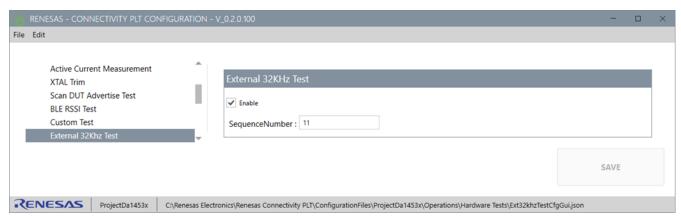


Figure 61. Ext32kHz crystal test configuration

8.3.11 GPIO Get Test



Figure 62. GPIO get configuration

8.3.12 GPIO Set Test

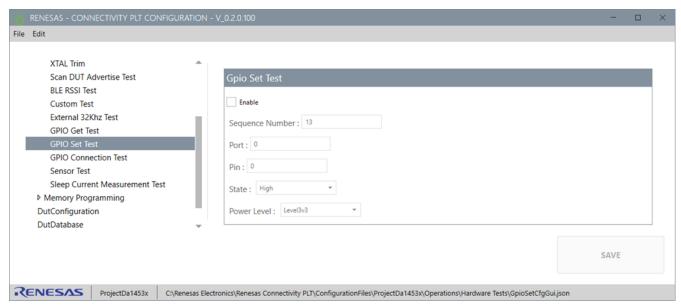


Figure 63. GPIO set configuration

8.3.13 GPIO Connection Test

If the **Is Short** option is enabled, the operation checks whether **Set Pin** has the same level as **Get Pin** for all retries. Alternatively, the operation checks whether **Get Pin** is always low no matter what the **Set Pin** level is.

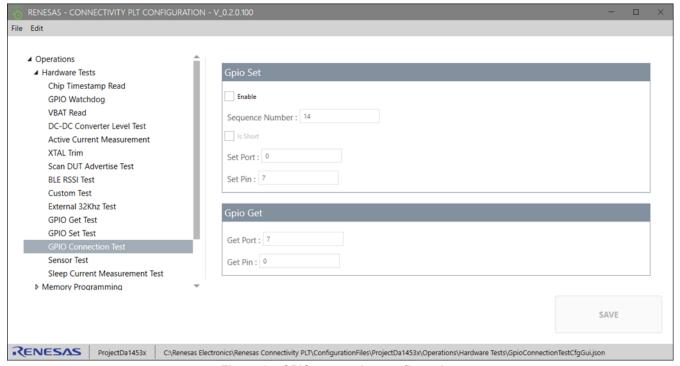


Figure 64. GPIO connection configuration

8.3.14 Sensor Test

The operation can perform read and write functions to the sensor at a specified register address. In the case of I2C devices the I2C address needs to be specified in 7-bit format. If the read function is used the **Expected Data** field is compared with the result to determine the success of the test. When the write function is used, it is followed by a read test to verify that the value written is correct, this determines the test result.

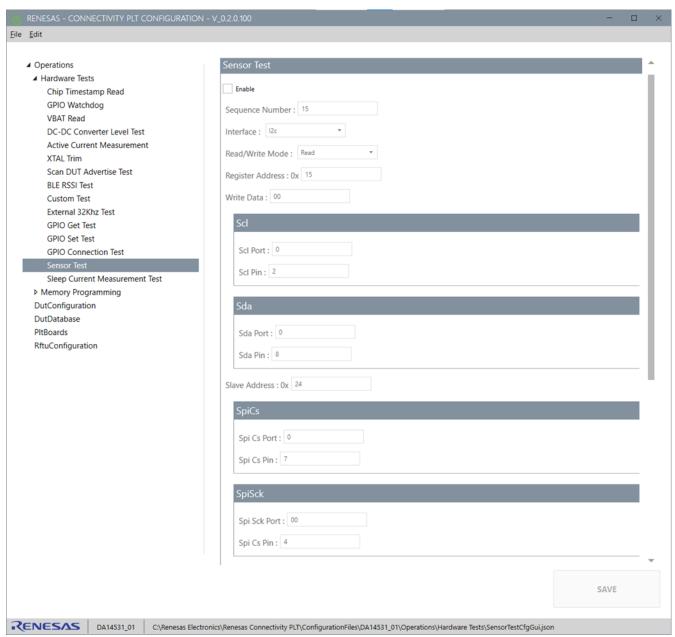


Figure 65. Sensor test configuration 1

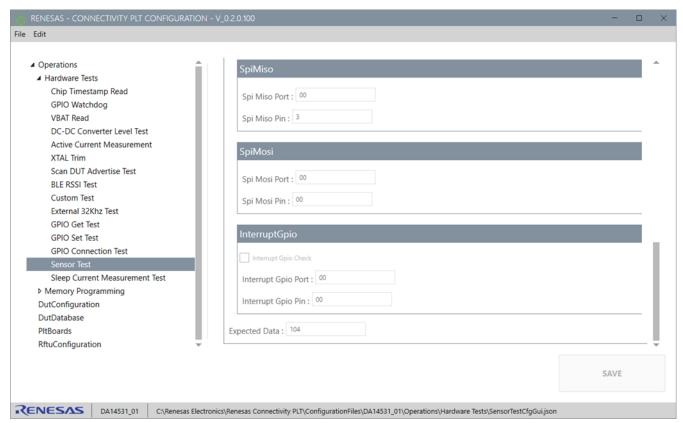


Figure 66. Sensor test configuration 2

8.3.15 Sleep Current Measurement Test

Due to the extremely low currents, an external DMM instrument is required for this operation to make very accurate measurements. For details on the instrument and connectivity, see Section 5.4.2. The measurement is performed on the VDUT power supply of the Connectivity PLT and is cumulative of the current from all DUTs. The result is divided by the number of active DUTs, report and compared to pass/fail criteria.

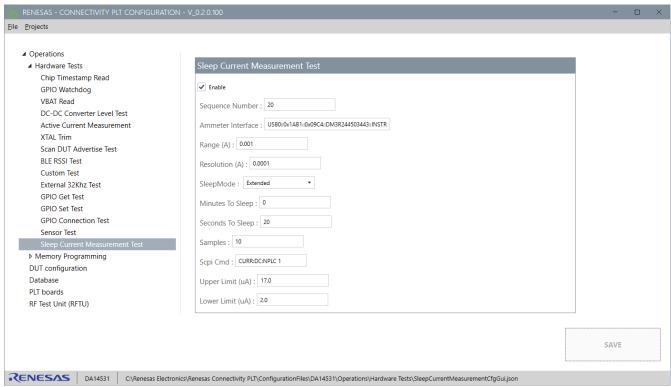


Figure 67. Sleep current measurement configuration

Configuration details:

- Ammeter Interface: the NI VISA address of the instrument (can be obtained by the NI Max application).
- Range: the set range of the instrument. The actual range values depends on the instrument. Typical values are 1 μA, 10 μ A, 100 μ A, 1 mA, 10 mA, 100 mA, 1 A, 3 A, 10 A. The value must be entered in ampere. Default value is 1 mA. This range must be able to accommodate the sleep current of all DUTs connected to a single Connectivity PLT board.
- Resolution: the set resolution for the instrument. The actual resolution depends on the instrument. The acceptable values are between 0 and 7 decimal places. Note that many instruments do not use this command and the range sets the resolution as well.
- Sleep mode: Sleep mode depends on the CPU supported modes, typically an active, extended and deep sleep mode is support. Current consumption differs between these modes.
- Minutes/Seconds to sleep: the time the device is set to wake up after switching to sleep mode. The CPU of the DUTs uses a timer interrupt to wake up since for the sleep operation most I/O is commonly disabled including the reset pin. These settings also determine the length of time after which the measurement is made which happens just before the device wakes up.
- Sample: the number of samples to be taken and averaged.
- SCPI CMD: additional SCPI command, usually specific to the instrument used. The default CURR:DC:NPLC 1 sets the sampling type to one NPLC cycle.
- Upper/Lower limits: sets the pass/fail criterial for the sleep current value per DUT.

8.4 Memory Programming Configuration

The memory programming group contains operations for reading and writing to different types of memories internal and external to the MCU. In addition to simple binary read/write operations special memory areas can be configured and programmed.

Table 26 summarizes all memory programing operations.

Table 26. Types of memory tests

Operation type	Description
UART Baudrate Set	Sets the baud rate of the UART for all memory operations. See Section 8.4.1.
SPI Flash Init	Initializes the external flash memory controller which internally defines the pins used and other settings as configured in the peripheral configuration page. See Section 8.4.2.
SPI Flash Erase All	Performs a chip erase on the flash memory. See Section 8.4.3.
SPI Flash Erase Block	Erases specific memory blocks. See Section 8.4.4.
SPI Flash Write Binary	Writes an entire binary to flash memory. See Section 8.4.5.
SPI Flash Read	Reads the flash memory with the specified settings. See Section 8.4.6.
EEPROM Memory Write	Writes an entire binary to an external EERPOM memory. See Section 8.4.7.
EEPROM Memory Read	Reads data from external EEPROM memory. See Section 8.4.8.
OTP Memory Write	Writes an entire binary to the OTP memory. See Section 8.4.9.
OTP Memory Read	Reads data from the OTP memory. See Section 8.4.10.
Header Write	Writes in the special memory area of OTP Header. See Section 8.4.11.
Configuration Script Write	Writes entries to the configuration script area of the OTP. See Section 8.4.12.
Custom Memory Data Write	Writes data to Flash or OTP memory that are stored in the devices database and are specific for each serial number. See Section 8.4.13.
Common Memory Data Write	Writes data to Flash or OTP memory that are stored in the devices database. See Section 8.4.14.

8.4.1 Uart BaudRate Set

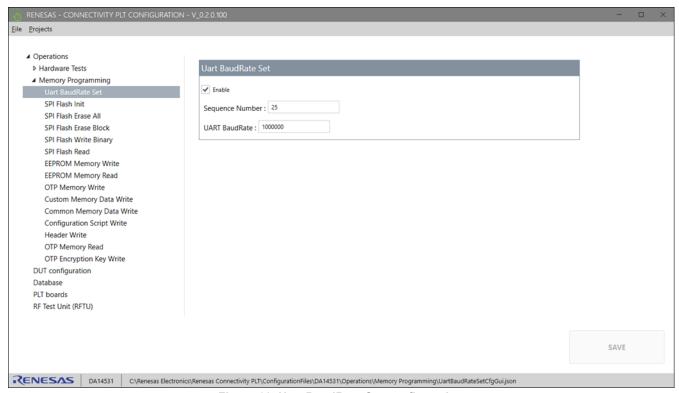


Figure 68. Uart BaudRate Set configuration

Table 27. Uart BaudRate Set configuration

Option	Description
Enable	This enables the UART Set baud rate operation.
Sequence Number	The order in which the test is run in execution
UART BaudRate	The baud rate to set up in bps
	9600, 19200, 57600, 115200, 1000000
	Note: if the default 115200 the operation doesn't need to be enabled.

8.4.2 SPI Flash Init



Figure 69. SPI Flash Init configuration

Table 28. SPI Flash Init configuration

Option	Description
Enable	This enables the SPI Flash Init operation.
Sequence Number	The order in which the test is run in execution
SPI Pins Enable	Enables the SPI pins

8.4.3 SPI Flash Erase All

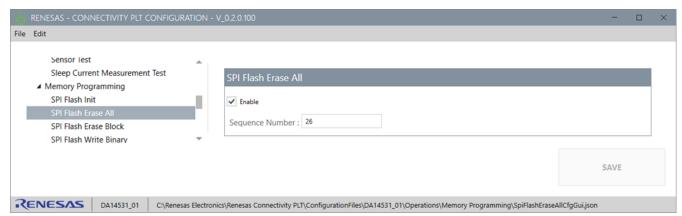


Figure 70. SPI Flash Erase All configuration

Table 29. SPI Flash Erase All configuration

Option	Description
Enable	This enables the SPI flash chip erase operation.
Sequence Number	The order in which the test is run in execution.

8.4.4 SPI Flash Erase Block

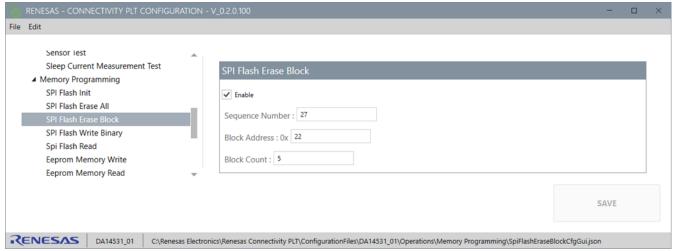


Figure 71. SPI Flash Erase Block configuration

Table 30. Flash erase block configuration

Option	Description
Enable	This enables the specific memory erase test.
Sequence Number	The order in which the test is run in execution.
Block Address	Configures the address of the first block.

Option	Description
Block Count	Number of memory blocks to erase

8.4.5 SPI Flash Write Binary

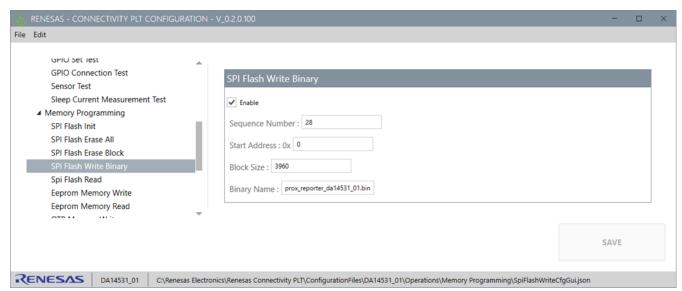


Figure 72. SPI Flash Write configuration

Table 31. Flash write configuration

Option	Description
Enable	This enables specific flash image programming operation.
Sequence Number	The order in which the test is run in execution
Start address	Configures the flash start address the image is written to.
Block Size	The chunk size for writing.
Binary Name	The filename of the binary to be written.
	Note: All binary files need to be stored in the Firmware folder under the installation folder and registered in the specific MCU JSON file.

8.4.6 SPI Flash Read

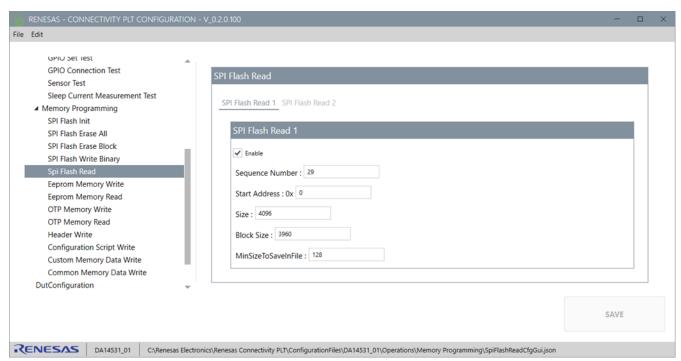


Figure 73. SPI Flash Read configuration

Table 32. SPI Flash Read configuration

Option	Description
Enable	This enables specific memory reading operation.
Sequence Number	The order in which the test is run in execution.
Start address	Configures the address the read operation begins from.
Size	Number of bytes to read, up to 64 MB. If data to be read are greater than
Block Size	The size of the chunk the data is split during reading.
MinSizeToSaveInFile	Minimum number of bytes required for the read operation to create a file. The file is stored under logs\folder mem_read_test in the Connectivity PLT installation folder. If no file is created the data is available in the logs files.

8.4.7 EEPROM Memory Write

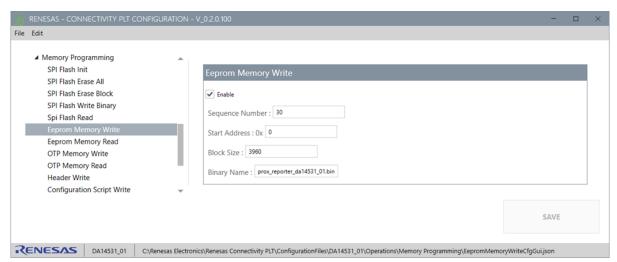


Figure 74. EEPROM Memory Write configuration

Table 33. EEPROM Memory Write configuration

Option	Description
Enable	This enables the specific memory reading operation.
Sequence Number	The order in which the test is run in execution.
Start address	Configures the start address.
Block Size	The size of the chunk the data is split during writing.
Binary Name	The filename of the binary file.
	Note: All binary files need to be stored in the Firmware folder under the installation folder and registered in the specific MCU JSON file.

8.4.8 EEPROM Memory Read

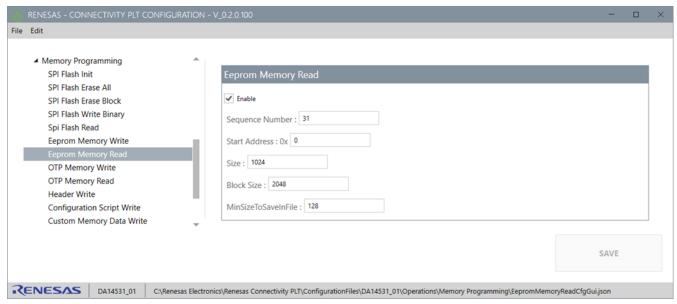


Figure 75. EEPROM Memory Read configuration

Table 34. EEPROM Memory Read configuration

Option	Description
Enable	This enables the specific memory reading operation.
Sequence Number	The order in which the test is run in execution.
Start address	Configures the start address.
Size	Number of bytes to read, up to 64 MB.
Block Size	The size of the chunk the data is split during reading.
MinSizeToSaveInFile	Minimum number of bytes required for the read operation to create a file. The file is stored under logs\folder mem_read_test in the Connectivity PLT installation folder. If no file is created the data is available in the logs files.

8.4.9 OTP Memory Write

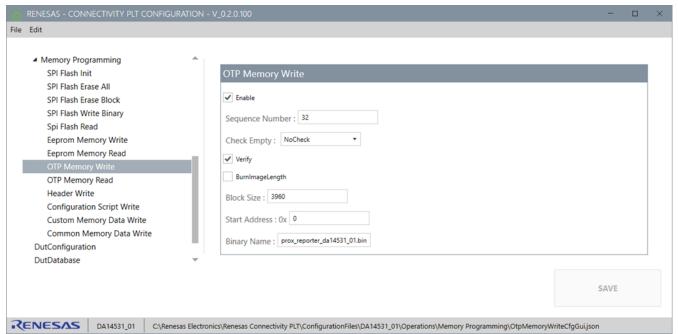


Figure 76. OTP Memory Write configuration

Table 35. OTP Memory Write configuration

Option	Description
Enable	This enables the specific memory reading operation.
Sequence Number	The order in which the test is run in execution
Check Empty	■ NoCheck writes the data without reading first
	■ ErrorlfNotEmpty fails the operation if the OTP area to be written is not empty
	■ PassifNotEmpty skips the writing and report the operation as pass.
	 PassifMatch fails the operation if the contents of the OTP differ from the binary file.
Verify	By selecting this option, the PLT software reads back the contents of the OTP memory and compares them to the original image file. If these do not match, the operation fails.
BurnImageLength	This option writes the size of the image written to the OTP Header.
Block Size	The size of the chunk the data is split during the operation.

8.4.10 OTP Memory Read

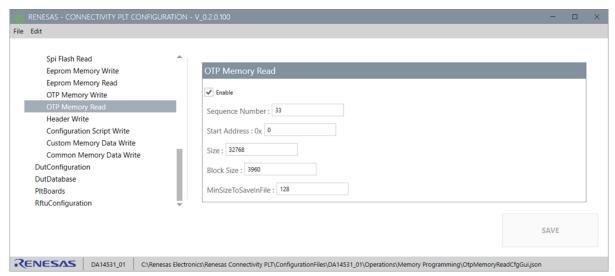


Figure 77. OTP Memory Read configuration

Table 36. OTP Memory Read configuration

Option	Description
Enable	This enables the specific memory reading operation.
Sequence Number	The order in which the test is run in execution.
Start address	Configures the start address.
Size	Number of bytes to read, up to 64 MB.
Block Size	The size of the chunk the data is split during the operation.
MinSizeToSaveInFile	Minimum number of bytes required for the read operation to create a file. The file is stored under logs\folder mem_read_test in the Connectivity PLT installation folder. If no file is created the data is available in the logs files.

8.4.11 Header Write

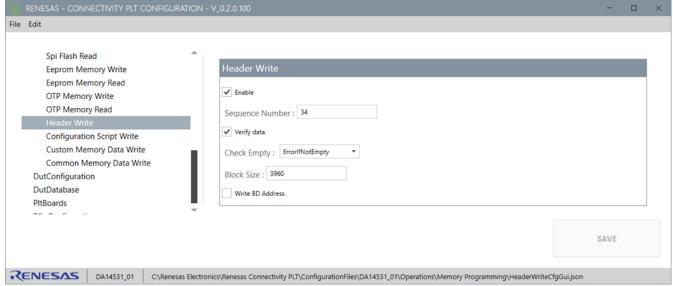


Figure 78. Header Write configuration

Table 37. Header Write configuration

Option	Description
Enable	This enables the header write operation.
Sequence Number	The order in which the test is run in execution.
Verify Data	By selecting this option, the PLT software reads back the contents of the flash memory and compares them to the original image file. If these do not match, the memory programming fails.
Check Empty	 NoCheck writes the data without reading first. ErrorlfNotEmpty fails the operation if the OTP area to be written is not empty. PassifNotEmpty skips the writing and report the operation as pass. PassifMatch fails the operation if the contents of the OTP differ from the one set to write.
Block Size	The size of the chunk the data is split during the operation.

8.4.12 Configuration Script Write

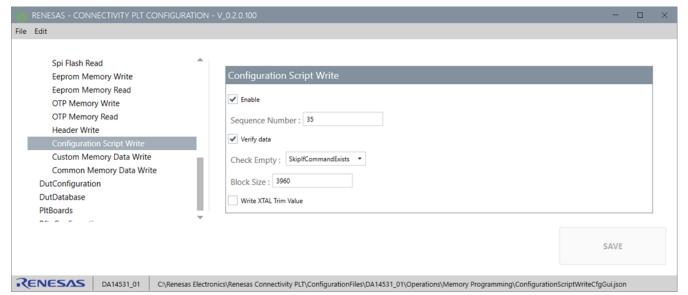


Figure 79. Configuration Script Write

Table 38. Configuration Script Write

Option	Description
Enable	This enables the Configuration Script write operation.
Sequence Number	The order in which the test is run in execution.
Verify Data	By selecting this option, the PLT software reads back the contents of the flash memory and compares them to the original image file. If these do not match, the memory programming fails.
Check Empty	No Check writes the data without reading first
	 ErrorlfCommandExists fails the operation if the CS entry command already exists in the CS area.
	 SkiplfCommandExists skips the command-value set if it already exists in the CS area.
	SkiplfTotalMatch fails the operation if the command-value set doesn't match what is already stored in CS area.
Block Size	The size of the chunk the data is split during the operation.
Write XTAL Trim Value	Write the XTAL Trim Value (acquired from XTAL trim test).
Write KDCO Calibration Value	Write the KDCO calibration value (acquired from the KDCO calibration test).

Option	Description
Write RC32 Calibration Value	Write the RC32 calibration value (acquired from the RC32 calibration test).

8.4.13 Custom Memory Data Write

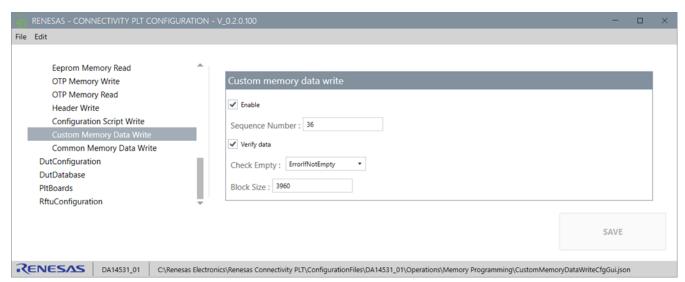


Figure 80. Custom Memory Write configuration

Table 39. Custom Memory Write configuration

Option	Description
Enable	This enables custom memory data write operation.
Sequence Number	The order in which the test is run in execution.
Verify Data	By selecting this option, the PLT software reads back the contents of the flash memory and compares them to the original image file. If these do not match, the memory programming fails.
OTP Check Empty	Not implemented for this operation – Set to No Check.
Block Size	The size of the chunk the data is split during the operation.

8.4.14 Common Memory Data Write



Figure 81. Common Memory Write configuration

Table 40. Common Memory Write configuration

Option	Description
Enable	This enables common memory data write operation.
Sequence Number	The order in which the test is run in execution.
Verify Data	By selecting this option, the PLT software reads back the contents of the flash memory and compares them to the original image file. If these do not match, the memory programming fails.
Check Empty	Not implemented for this operation – Set to No Check.
Block Size	The size of the chunk the data is split during the operation.

9. Connectivity PLT Application

The Renesas Connectivity PLT application serves as the primary graphical user interface for executing tests and programming tasks. It provides operators with a console to initiate and monitor the testing process. The application connects remotely to the Connectivity PLT Core service and functions as the front end of the PLT system. It can be launched either from the Windows Start menu or by directly running the executable file located in the installation directory. (Renesas Connectivity PLT.exe).

9.1 Connectivity PLT Application Main Execution Window

The main application window consists of tiles, each representing a DUT and its status, as well as a list of operations and their status, a start/finish button, and several other information fields. Figure 82 shows an example of a setup of a single Connectivity PLT board with 8 DUTs.

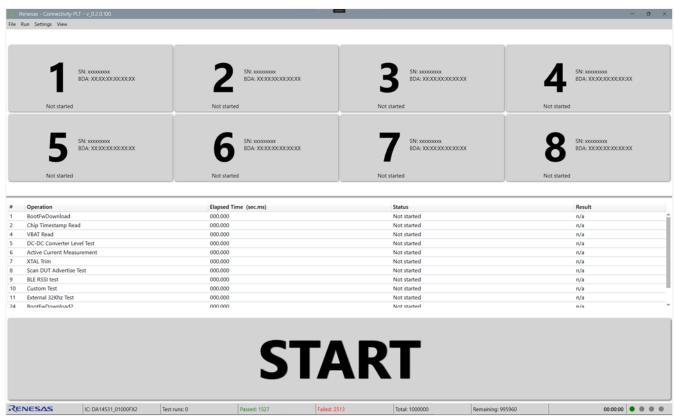


Figure 82. Test execution start window

You can configure the testing using the menu items at the top of window. Brief testing results are displayed at the bottom of the window, including the four LEDs for RFTU status (grey for not enabled, green for enabled and detected, and red for enabled but not detected).

Information tiles with numbers represent DUTs in your setup (Figure 83) and can accommodate from one to four Connectivity PLT boards consisting of one to thirty-two DUT tiles (one to eight DUTS per Connectivity PLT board). The layout is configured using X/Y axis in PLT boards Configuration, see Section 8.2.3.



Figure 83. DUTs grid

Each DUT tile contains the following:

- a Display name (for example, 01) as configured in Connectivity PLT boards settings.
- b Acquired Serial Number either automatically or from the initial dialog. (only while tests are running)
- c Acquired board address as fetched automatically form the devices database (either based on entered serial number or automatic base on next available) (only while tests are running)
- d Current operation executing (only while tests are running), see Figure 84. If any of the DUTs fails, the current command field indicates the failed test command.

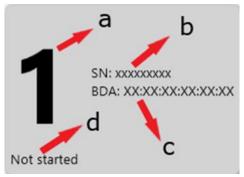


Figure 84. Single DUT tile

A splitter control allows the display area to be maximized for showing more of the operations table or more tile space depending on the user needs.



Figure 85. Grid splitter top position



Figure 86. Grid splitter bottom position

The operations grid is the table that shows the operations that are enabled to run. This table provides data about execution time, status, and results (Figure 87).

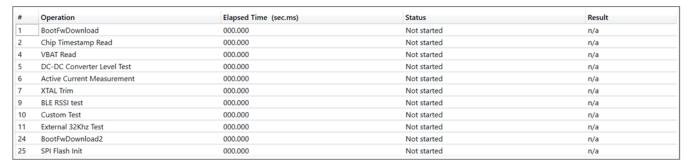


Figure 87. Operations grid

Start button has four states:

- Idle grey and enabled; right click the button or press space bar to start testing.
- Enter Device Serial Number at this state a dialog is displayed requesting to enter the serial number
- Running blue and disabled; testing is in process.
- Finish green if testing is successful or red if testing failed.

You can also use keyboard shortcuts: to start testing, select S or the Spacebar; and to finish testing, select F.

9.2 Test Execution

The test execution process has the following stages:

1. Serial numbers assignment (optional)

If the Device Specific Serial Number option was enabled a dialog to enter the first serial number is displayed when the test process is initiated, see Figure 88.

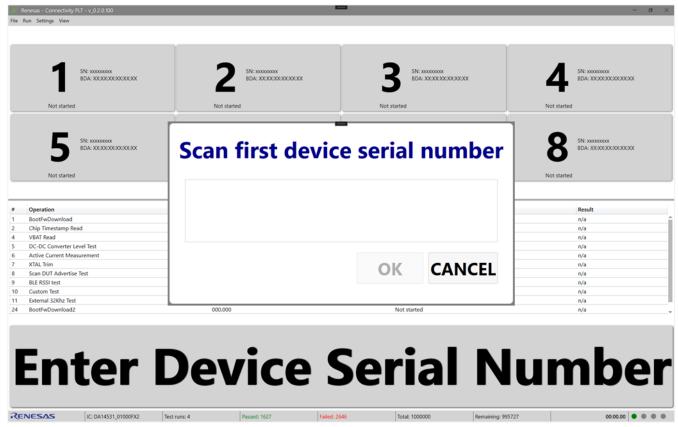


Figure 88. Enter serial number screen

After the serial number is entered, all DUTs are assigned with a sequential serial number retrieved from the database along with the corresponding Bluetooth address.

2. Configuration

Connectivity PLT fetches the latest configuration available in the current project. If changes are made to the configuration, reload is required to apply these changes (go to **File >Reload Configuration** or press F5). Even if manual reload is not executed the configuration is going to be reloaded at the beginning of the test process and a warning message appears, see Figure 89.

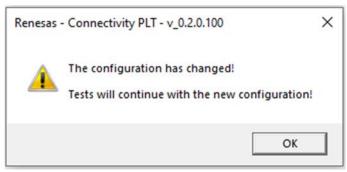


Figure 89. Configuration reload warning

3. OTP Write Warning

If any operation includes writing to the OTP memory, a warning is displayed at the start of the test process to avoid accidental writes since the OTP cannot be re-written. The warning can be suppressed for future runs from the same dialog by checking the Don't ask again for the current session checkbox.

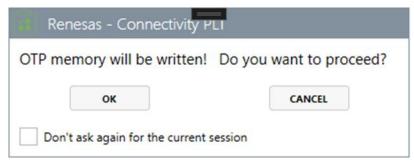


Figure 90. OTP write warning message

4. Tests Execution

When the test process starts, the background color of DUT tiles changes to blue to indicate the in progress status. The active operation row text color changes to blue also to indicate in progress while also the dedicated test timer starts. The start button is disabled but serves as a progress bar colored blue while executing and green or red depending on the result, see Figure 91.



Figure 91. Test execution

If any DUT fails on any operation, the tile background becomes red, the failed command is displayed at the bottom of the tile, and the operation row text color changes to red to indicate that at least one DUT failed this test.



Figure 92. DUTs fail during execution

5. Test process completion

• Successful completion – if all operations were successful (Pass) for all the DUTs tiles, lines in the operations table, and the start button are green.

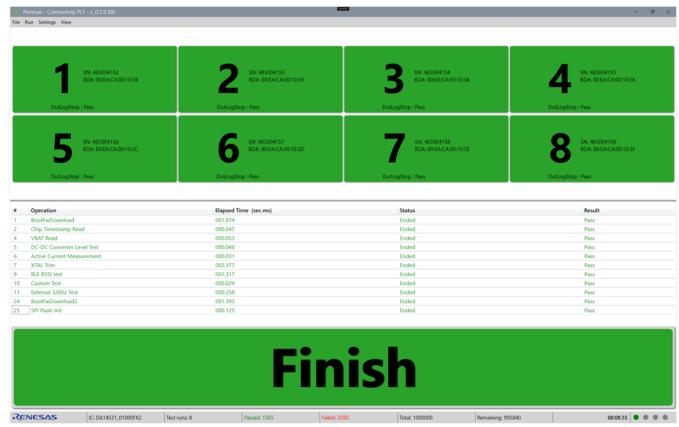


Figure 93. Successful test sequence

· Incomplete testing due to failures.

If during the test process all DUTs have at least one test that failed, then the test process stops as no more DUTs are available to continue. For this case, all DUT tiles are red whilst the operations table displays in red all the operations that failed for at least one DUT. Figure 94 shows that DUTs 1 and 6 failed on GPIO Connection Test and DUTs 2,3,4,5,7, and 8 failed in BootFwDownload. Failed command is indicated on each DUT tile.

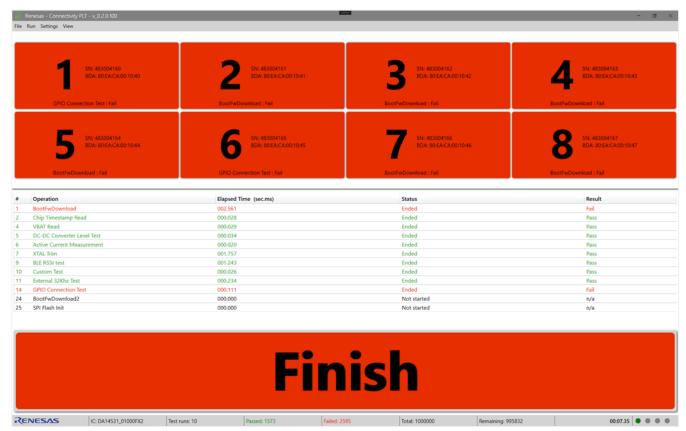


Figure 94. Failed test sequence

Partially successful completion

The testing is considered partially successful when there are both passed and failed DUTs. Figure 95 shows that DUT 4 failed on BLE RSSI test but 1,2,3,5,6,7,8 passed the test sequence. Successful DUTs are green, failed are red, failed operation and start button is red.

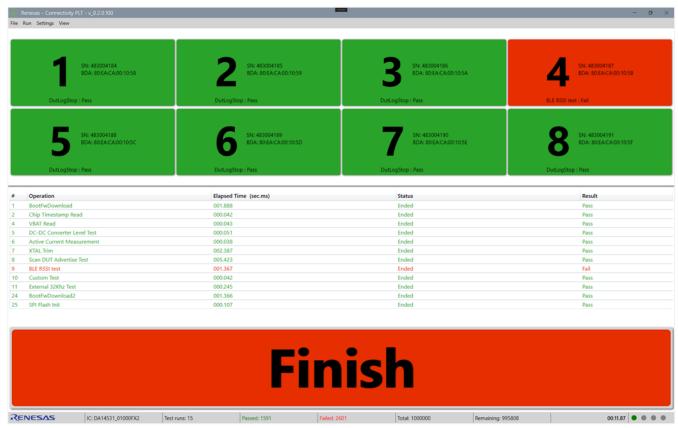


Figure 95. Partially successful test sequence

6. Test Logs viewing

After the termination of the test sequence, clicking any tile brings up the log file for the specific DUT (Figure 96) or by opening the logs folder under the installation folder. (Figure 97).

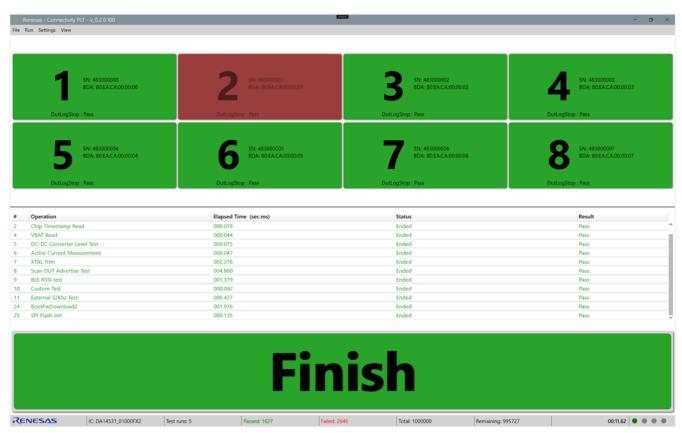


Figure 96. Click on DUT tile

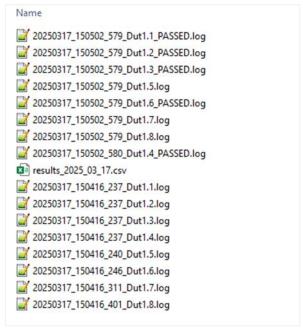


Figure 97. Example of the log folder contents

7. DUT Log viewing

The log file for each DUT contains a detailed log of the test process and the test results. It can be found in the logs folder or by clicking the DUT tile at the completion of the test process.

A header is included in the log file providing details about connectivity PLT hardware and the software. It includes the firmware and software versions, the station name and test dates and times. It also provides information about DUT, such as the physical connection to the Connectivity PLT hardware and the virtual COM port used, the serial number and BD address assigned. See Figure 98.



Figure 98. DUT log example

For the DUTs that have passed all tests, the log file is renamed with the word "_PASSED" at the end for easier retrieval.

The Log file is created at the beginning of each test, containing only the header and all information available at the time of creation. As the device testing progresses, the file is updated with the status of each test including information about the DUT and a timestamp of the event. After the tests finish the header is updated with the end time of the test and the firmware versions, which were retrieved during testing.

8. CSV Log viewing

In addition to the individual DUT logs all results are summarized in a continuous CSV log file. The CSV logs are located in the same folder as the DUT logs and are rotated in a daily basis. Every CSV file has a filename indicating the date created, for example "results_2024_10_15.csv".



Figure 99. CSV log example (part 1)



Figure 100. CSV log example (part 2)

9.3 Error Handling

Connectivity PLT switched to a demo mode when various configuration and hardware issues occur. Demo mode has no functionality, it only displays a basic setup screen, Figure 101.

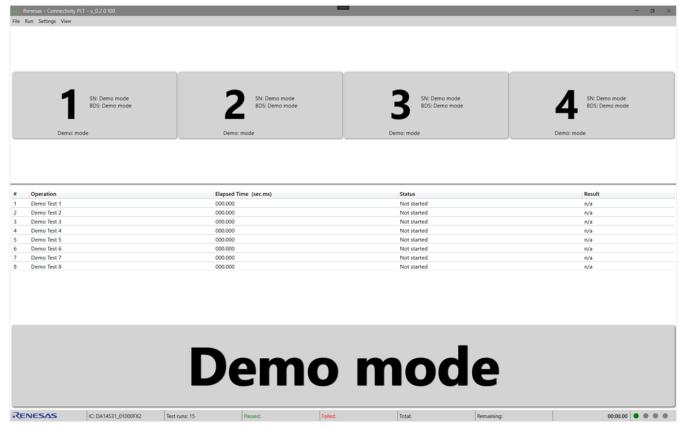


Figure 101. Demo mode

In some cases where there are issues in the initialization, a reload of the configuration might help resolve them. To reload the configuration, go to **File> Reload Configuration** or by press F5. Common causes of a failed initialization are communication errors between the different services that can happen on the first run of the application or connectivity issues with hardware. If a reload of the configuration doesn't solve the issue, check hardware connectivity and that the Connectivity PLT Core Service and Connectivity PLT Database Service are running.

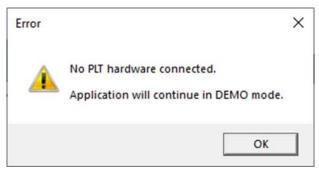


Figure 102. Hardware communication error

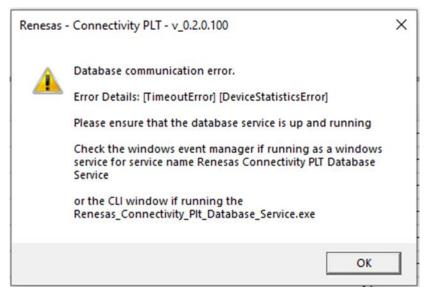


Figure 103. Database communication error

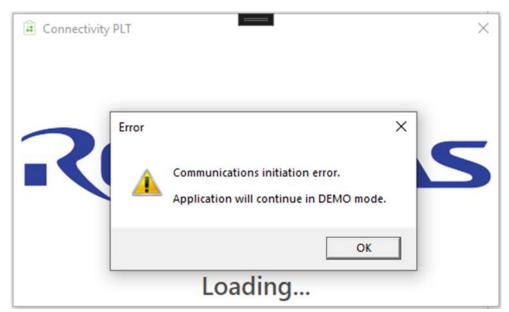


Figure 104. Core Service communication error

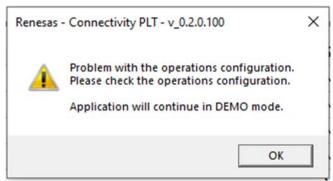


Figure 105. Operations configuration error

10. Connectivity PLT CLI Application

The Connectivity PLT CLI application (Renesas_Connectivity_PLT_Cli.exe) is a command line Interface application with functionality and features similar to the Connectivity PLT Application. In addition to the standard tasks for starting and monitoring the test process – based on the same configuration structure – there are additional commands available that can aid interoperability with other applications.

The application can be started from the start menu shortcut or by executing Renesas_Connectivity_PLT_Cli.exe in the installation folder. A command menu is displayed when the application is started with no parameters Figure 106. All the commands stated in this menu can also be used as parameters to automatically execute from the command line.

```
Renesas - Connectivity PLT CLI - v_0.2.0.100

Renesas - Connectivity PLT CLI - v_0.2.0.100

Commands

Description

f --> Start communication with CoreService

s --> Start test execution

<pe
```

Figure 106. Execution CLI start screen

Table 41. CLI commands

Command	Arguments	Description
f	-	Establishes communication with CoreService.
S	First DUT serial number	Starts the test sequence.
1	<pltboardaddress> <dutid></dutid></pltboardaddress>	Returns the full log file path of a specific DUT. Log files are accessible only after running the test sequence.
0	-	Returns the operations test sequence.
		The operations list can be configured on Renesas_Connectivity_PLT_Configuration.
r	-	Returns the overall statistics: total devices, remaining devices, passed and failed DUTs.
У	-	Returns the MCU name.
m	<repetitions></repetitions>	Runs the test sequence on repeat, according to the number of repetitions entered.
d	<number duts="" of=""></number>	Gets the next available DUT information from the database (S/N and BD Address).
g	-	Gets the RFTU status (name, type, activity, connection).
h	-	Returns the menu options.
е	-	Exits the application.

11. Connectivity PLT Core Service

The Connectivity PLT Core Service is the central component of the PLT system and hosts a WebSocket service used by client applications, including the Connectivity PLT application and the Connectivity PLT CLI.

This service must be installed on the Windows machine that is directly connected to the Connectivity PLT hardware through USB. The Core Service can operate in two modes:

- As a Windows Service runs in the background automatically with no user interaction required.
- As a CLI Application runs in a command-line interface for manual control and special functions.

Under normal circumstances, the service runs silently in the background, requiring no user interaction. However, for advanced tasks or special operations within the Connectivity PLT system, the service must be run in CLI mode to provide an interface for these functions.

11.1 Operation in Service Mode

In Service mode, the Connectivity PLT Core Service acts as the link between the hardware and the user applications, while also serving as the executor for all operations. When a request is received from a client application, the service loads the relevant configuration files that define the parameters for the requested operation.

In addition to handling direct communication with the hardware, the service is responsible for the detection, configuration, and initialization of Connectivity PLT boards, RFTUs, and DUTs.

The Core Service remains idle until a client connects and begins issuing commands. Once a request is received, the Core Service executes the required operations, providing real-time updates to the client throughout the process. Upon completion, it returns the results to the client. The operations' sequences depends on the parameters and commands listed in the configuration files and does not depend on the continued commands form the client.

The Connectivity PLT Core Service communicates to the user front end (graphical or CLI) using messages. Both request and reply messages consist of the Message Type ID field and parameters field. The Type Id field is an integer number, identifying the type of data. This field has the same value for both request and reply to messages.

Table 42 shows the requests and the corresponding reply messages supported by the Core Service.

Table 42. Core service messages

Message type	Message type ID	Description
Start Test	2	CoreService starts test execution
Dut Status Update	10	DUT status update info is sent to the Client
Rftu Status Update	11	RFTUs' status update info is sent to the Client
PltBoard Configuration	14	PLT Boards Configuration info is sent to the Client
Dut Log FilePath	15	DUT log file path info is sent to the Client
Operations	16	Operations list info is sent to the Client
Device Statistics	17	Device Statistics info from the Database is sent to the Client
Dut Mcu Name	18	The name of the DUT's MCU is sent to the Client
Device Info	19	Device info list from the Database is sent to the Client

Table 43 shows a list of error messages.

Table 43. Core service error messages

Error message	Error ID	Description
NoError	0	Successful request, no error returned from CoreService.
NoPltBoardError	1	No connected PLT board found.
PltBoardNumberError	2	Error in the number of PLT boards connected.

Error message	Error ID	Description
PltBoardAddressingError	3	Error in PLT Boards addressing. Probably a misconfiguration of the PLT boards' DIP switches.
DutDatabaseError	4	Error of the Database communication.
UsbChainError	5	Error in the PLT board daisy chaining setup.
DutLogFilePathError	6	Error in retrieving the DUT log file path.
OperationsError	7	Error in getting the Operations list.
StartTestsError	8	Error when attempting test execution.
TimeoutError	9	Timeout error in the communication between the client and the server.
CommsInitError	10	Error of CoreService - PLT Client application connection.
DeviceStatisticsError	11	Error in retrieving Device Statistics from the Database.
DutMcuNameError	12	Error when attempting to get the MCU name of a DUT.
DeviceInfoError	14	Error in retrieving Device Info from the Database.
RftuConfigurationError	15	Error in the configuration of the RFTUs.
RftuConnectionError	16	Error of RFTU connection.
SerialNumberNotFoundError	17	Error in getting a given Serial Number from the Database.
OtherError	13	Other error cases, not described above in this table.

11.2 Operation in CLI Mode

If the Connectivity PLT Core Service is installed as a windows service (see Section 6.2) it is required to stop the windows service before starting it in CLI mode. This can be done through the Connectivity PLT Service Agent or any other of the standard Windows methods of starting and stopping services (Services Application, PowerShell, Command prompt). The service name is **Renesas Connectivity PLT CoreService.**

The Core Service can be started through the shortcut in the start menu or by launching command prompt and executing Renesas_Connectivity_PLT_CoreService.exe CLI within the installation folder, note the additional parameter CLI.

Note that while in IDLE state, a client can connect to the Core Service same as if it was running in the background service, Figure 107.

Many of the functions at this stage fall outside the scope of this user manual as they are mainly used for development purposes. All the user functionality can be accessed through the dedicated Connectivity PLT CLI application (see Section 10).

```
Renesas - Connectivity PLT CoreService - v_0.2.0.100
                                                                                                                                         Renesas - Connectivity PLT CoreService - v_0.2.0.100
C:\Renesas Electronics\Renesas Connectivity PLT\
ENV CDIR:C:\Renesas Electronics\Renesas Connectivity PLT\
select module to see available commands:
 Mcu
McuI2c
 McuGpio
McuAdc
  McuSpi
  Ina231
  ResetVoltage
  DutVoltage
DutAuxVoltage
  VddioVoltage
McuSpiFlash
  Ftdi
  Fpga
Duts
  Flash Programmer
AtCommands
  AmmeterScpiCommands
  DutLogging
  CoreService
  ExecutionService
  Companion
```

Figure 107. Core Service in CLI mode initial screen

Running the Core Service in CLI mode allows attaching a dedicated companion board to each Connectivity PLT main board to perform self-testing and calibration. Once the companion board is attached the test process can be initiated by the Core Service in CLI mode.

Following the main screen, type Companion to enter the companion boards test menu. Following this type StartTests 1 to start the test process. The parameter 1 is the number of iterations to perform, Figure 108.

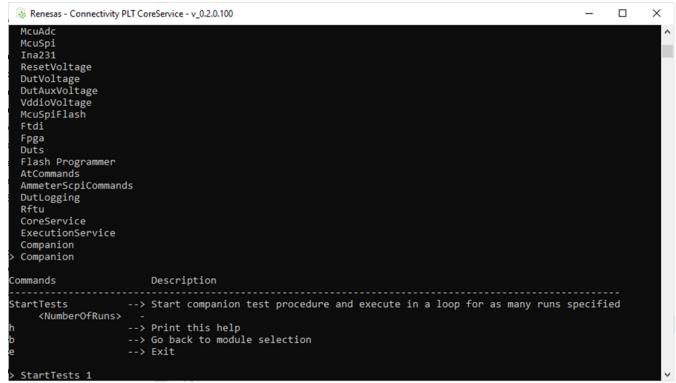


Figure 108. Companion board tests

The Core Service runs through a number of tests as defined in the CompanionTests.json in the configuration files folder. Following the completion of the test process a pass/fail message is displayed. The pass/fail criteria can be adjusted depending on the standards of the production line.

12. Connectivity PLT Service Agent

The Connectivity PLT Service Agent is a small application designed to be present in the system tray to provide a quick way to start and stop the Connectivity PLT windows services as well as offer a live real time log of the Connectivity PLT Core Service execution. The application is installed automatically, and a shortcut is placed in the windows all-users start-up folder, so that it automatically starts after a reboot of the system.

The Service Agent can be started manually from the start menu or automatically during windows start. The tray icon is located either directly on the visible tray or on the extended tray which can be shown by clicking the tray icon expansion arrow, Figure 109.



Figure 109. Service Agent icon

By clicking the icon, the Service Agent menu appears where the Core Service and Database services can be started and stopped, as well as a live view of the Core Service Log can be started, Figure 110.

The Core Service Console can be used to monitor the communication between the Connectivity PLT application and the Core Service as well as the status of the operations, Figure 111.

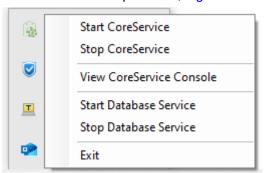


Figure 110. Service Agent menu

```
Renesas Connectivity PLT Service Agent
WebSocket connection opened from 127.0.0.1:57942/ws://127.0.0.1:7000/PltWebSocketService
Received command from Ws client: [DeviceStatisticsGet]
Received message type 17 -DeviceStatistics Get
Sending reply data to client...
Data sent to client
Received command from Ws client: [PltBoardConfiguration]
Received message type 14 - PltBoardListConfiguration Get
Sending reply data to client...
Data sent to client
Received command from Ws client: [DutMcuNameGet]
Received message type 18 - DutMcuNameGet
Sending reply data to client...
Data sent to client
Received command from Ws client: [OperationsGet]
Received message type 16 -Operations Get
Sending reply data to client...
Data sent to client
Received command from Ws client: [CoreRftuStatusUpdate]
Received message type 11 - CoreRftuStatusUpdate Get
Plt Num [0] <-> Plt Address [1]
 - RFTU[RFTU Ble0] -> Enabled - [Connected] - BleVersion=[11.0.1.0], AppVersion=[PLT_v4.6.0] on COM76 for PLTs
[First]
 - RFTU[RFTU Blel] -> Disabled - [Disconnected]
  RFTU[RFTU Ble2] -> Disabled - [Disconnected]
RFTU[RFTU Ble3] -> Disabled - [Disconnected]
Sending reply data to client...
Data sent to client
```

Figure 111. Service Agent Core Service log view

13. Connectivity PLT Firmware Update Application

The Connectivity PLT Firmware Update application (Renesas_Connectivity_PLT_Firmware_Update.exe) is a tool to update the SPI Flash memory of the MCU and the FPGA.

NOTE

For PLT Firmware Update Application to work, the SAM-Ba driver should be installed. See Section 6.4.

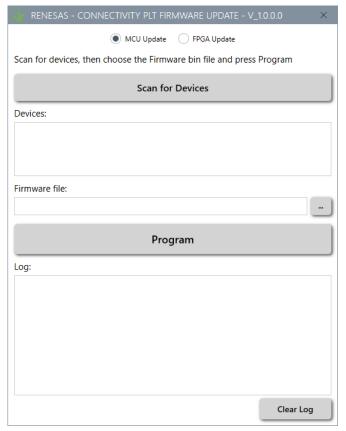


Figure 112. Firmware update application initial screen

13.1 MCU Update

To update MCU firmware:

- 1. In the top of Renesas Connectivity PLT Firmware Update window, select MCU Update, and then click Scan for Devices (Figure 112).
- 2. If the hardware is connected correctly, you should see from one to four USB-IO devices corresponding to each connected PLT board, see Figure 113.

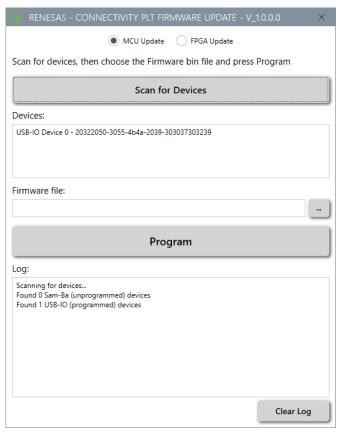


Figure 113. Device detection

3. Next specify the **Firmware file**, click the browse button (three dots), and select the appropriate file to flash, see Figure 114.

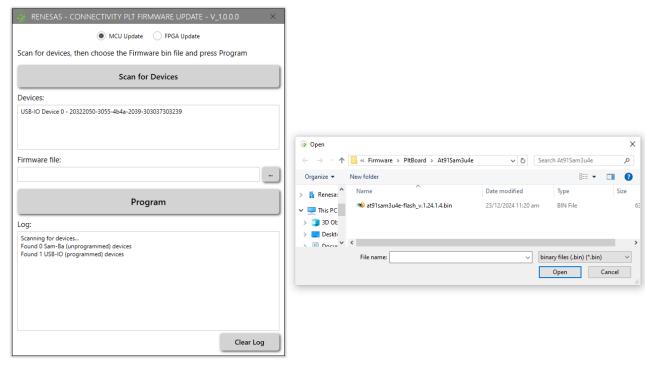


Figure 114. Firmware update file browse

4. Click Program. See Figure 115 and Figure 116.



Figure 115. Firmware update - .bin file loading

5. Check the log for errors.

Figure 117 shows the example log.



Figure 116. Firmware update - Programing

```
Scanning for devices...
Found 0 Sam-Ba (unprogrammed) devices
Found 1 USB-IO (programmed) devices
Starting update..
Scanning for devices...
Found 0 Sam-Ba (unprogrammed) devices
Found 1 USB-IO (programmed) devices
[FwUpdate] Started: Will update MCU on PLT board=[0 - 20322050-3055-4b4a-2039-303037303239] using
firmware file=[C:\Renesas Electronics\Renesas Connectivity PLT\Firmware\PltBoard\At91Sam3u4e
\at91sam3u4e-flash_v.1.24.1.4.bin]
[FwUpdate] BootFromRomStarted: Configuring boot from ROM, erasing flash and reseting...
[FwUpdate] BootFromRomCompleted: Completed boot from ROM and reset
[FwUpdate] FlashingStarted: Starting flashing..
[FwUpdate] Message: Found SamBa devices:
[FwUpdate] Message: COM3 - AT91 USB to Serial Converter (COM3)
[FwUpdate] Message: Will update SamBa device: COM3 - AT91 USB to Serial Converter (COM3)
[FwUpdate] SamBaScriptMessage: "arguments:"
[FwUpdate] SamBaScriptMessage: Prog_uli_with_Sam-Ba.cmd
[FwUpdate] SamBaScriptMessage: "C:\Renesas Electronics\Renesas Connectivity PLT\Firmware\PltBoard
\At91Sam3u4e\at91sam3u4e-flash_v.1.24.1.4.bin
[FwUpdate] SamBaScriptMessage: COM3
[FwUpdate] SamBaScriptMessage: "C:\Program Files (x86)\Atmel\sam-ba_2.18\sam-ba.exe"
[FwUpdate] SamBaScriptMessage: ECHO is off.
[FwUpdate] SamBaScriptMessage: "sam-ba exit code" 1
[FwUpdate] Message: Mcu Update Successful
Scanning for devices...
Found 0 Sam-Ba (unprogrammed) devices
Found 1 USB-IO (programmed) devices
Starting update...
Scanning for devices..
Found 0 Sam-Ba (unprogrammed) devices
Found 1 USB-IO (programmed) devices
[FwUpdate] Started: Will update MCU on PLT board=[0 - 20322050-3055-4b4a-2039-303037303239] using
firmware file=[C:\Renesas Electronics\Renesas Connectivity PLT\Firmware\PltBoard\At91Sam3u4e
\at91sam3u4e-flash_v.1.24.1.4.bin]
[FwUpdate] BootFromRomStarted: Configuring boot from ROM, erasing flash and reseting...
[FwUpdate] BootFromRomCompleted: Completed boot from ROM and reset
[FwUpdate] FlashingStarted: Starting flashing..
[FwUpdate] Message: Found SamBa devices:
[FwUpdate] Message: COM3 - AT91 USB to Serial Converter (COM3)
[FwUpdate] Message: Will update SamBa device: COM3 - AT91 USB to Serial Converter (COM3)
[FwUpdate] SamBaScriptMessage: "arguments:"
[FwUpdate] SamBaScriptMessage: Prog_uli_with_Sam-Ba.cmd
[FwUpdate] SamBaScriptMessage: "C:\Renesas Electronics\Renesas Connectivity PLT\Firmware\PltBoard
\At91Sam3u4e\at91sam3u4e-flash_v.1.24.1.4.bin
[FwUpdate] SamBaScriptMessage: COM3
[FwUpdate] SamBaScriptMessage: "C:\Program Files (x86)\Atmel\sam-ba_2.18\sam-ba.exe"
[FwUpdate] SamBaScriptMessage: ECHO is off.
[FwUpdate] SamBaScriptMessage: "sam-ba exit code" 1
[FwUpdate] Message: Mcu Update Successful
```

Figure 117. Example for firmware update log

13.2 FPGA Update

To update FPGA, follow the same steps as for the MCU update but instead select **FPGA Update** and the appropriate .bin file.

Appendix A Conformity Assessment

Connectivity PLT conforms to laws and regulations that are described in the following subsections.

A.1 FCC Notice (Applicable to Evaluation Kits not FCC-Approved)

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

A.2 CE – UKCA (Europe-UK)

The Connectivity PLT is tested and found to comply with **EMC Directive (2014/30/EU)** for electromagnetic compatibility. Applicable standards are the following:

■ EN 55032 (2015)/AC (2016)/A11 (2020) & EN 55035 (2017)/A11 (2020).

Simplified Declaration of Conformity

Hereby, Renesas Design Netherlands B.V. declares that The Connectivity PLT is in compliance with **EMC Directive (2014/30/EU)**. The full texts of the EU declaration of conformity are available at the following internet address: www.renesas.com

A.3 WEEE Directive (2012/19/EU)





The Waste Electrical and Electronic Equipment Regulations 2013



For customers in the UK and European Union

The WEEE (Waste Electrical and Electronic Equipment)

regulations put responsibilities on producers for the collection and recycling or disposal of electrical and electronic waste. Return of WEEE under these regulations is applicable in the UK and European Union.

This equipment (including all accessories) is not intended for household use. After use, the equipment cannot be disposed of as household waste, and the WEEE must be treated, recycled, and disposed of in an environmentally sound manner.



A.4 RoHS Compliance

Renesas Electronics' suppliers certify that its products are in compliance with the requirements of Directive 2011/65/EU of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment. RoHS certificates from our suppliers are available on request.

Table 44. Product standards

Revision	Description
ELOT EN 55032 E2:2015 +A11:2020	Electromagnetic compatibility of multimedia equipment – Emission Requirements.
ELOT EN 55035 E1:2017 +A11:2020	Electromagnetic compatibility of multimedia equipment – Immunity Requirements.

Table 45. Test standards

Revision	Description
ELOT EN 61000-4-2 E2:2009	Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques – Electrostatic discharge immunity test.
ELOT EN IEC 61000-4-3 E4:2020	Electromagnetic compatibility (EMC) – Part 4-3: Testing and measurement techniques – Radiated, radio-frequency, electromagnetic field immunity test.
ELOT EN 61000-4-8 E2:2010	Electromagnetic compatibility (EMC) – Part 4-8: Testing and measurement techniques – Power frequency magnetic field immunity test.

14. Revision History

Revision	Date	Description
01.02	Sept 12, 2025	Fixed J11 pinout.
01.01	Aug 14, 2025	Added Compliance information (Appendix A).
01.00	June 3, 2025	First version.

Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu Koto-ku, Tokyo 135-0061, Japan

www.renesas.com

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